US009081453B2

(12) **United States Patent**
Bulea et al.

(10) **Patent No.: US 9,081,453 B2**
(45) **Date of Patent: Jul. 14, 2015**

(54) **SINGLE LAYER CAPACITIVE IMAGING SENSORS**

(71) Applicant: **Synaptics Incorporated**, Santa Clara, CA (US)

(72) Inventors: **Mihai Bulea**, Santa Clara, CA (US); **Derek Solven**, San Jose, CA (US); **Joseph Kurth Reynolds**, Alviso, CA (US); **David Hoch**, Los Gatos, CA (US); **Tracy Scott Dattalo**, Santa Clara, CA (US)

(73) Assignee: **SYNAPTICS INCORPORATED**, San Jose, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 164 days.

(21) Appl. No.: **13/740,122**

(22) Filed: **Jan. 11, 2013**

(65) **Prior Publication Data**

US 2013/0181943 A1 Jul. 18, 2013

Related U.S. Application Data

(60) Provisional application No. 61/586,076, filed on Jan. 12, 2012.

(51) **Int. Cl.**
G06F 3/044 (2006.01)

(52) **U.S. Cl.**
CPC ***G06F 3/044*** (2013.01)

(58) **Field of Classification Search**
CPC G06F 2203/04111; G06F 2203/04112; G06F 2203/04113
USPC 345/173–174
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,087,625	A	5/1978	Dym et al.
4,233,522	A	11/1980	Grummer et al.
4,237,421	A	12/1980	Waldron
4,264,903	A	4/1981	Bigelow
4,293,987	A	10/1981	Gottbreht et al.
4,484,026	A	11/1984	Thornburg

(Continued)

FOREIGN PATENT DOCUMENTS

CN	2436978	Y	6/2001
CN	1490713	A	4/2004

(Continued)

OTHER PUBLICATIONS

International Search Report, PCT/US2013/021314 dated Jun. 25, 2013.

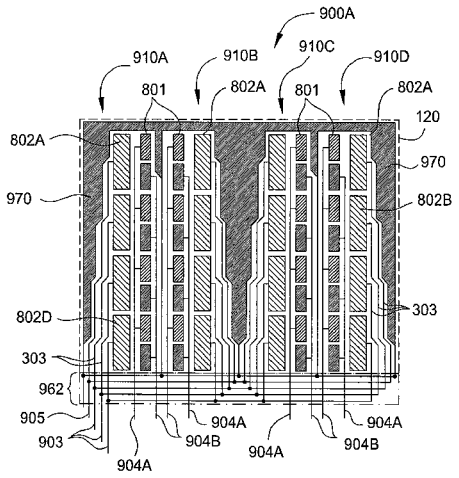
(Continued)

Primary Examiner — Kevin Nguyen
(74) *Attorney, Agent, or Firm* — Patterson + Sheridan, LLP

(57) **ABSTRACT**

Embodiments of the invention generally provide an input device that includes a plurality of sensing elements that are interconnected in desired way to acquire positional information of an input object, so that the acquired positional information can be used by other system components to control a display or other useful system components. One or more of the embodiments described herein, utilizes one or more of the techniques and sensor electrode array configuration disclosed herein to reduce or minimize the number of traces and/or electrodes required to sense the position of an input object within a sensing region of the input device.

17 Claims, 19 Drawing Sheets



(56) **References Cited**

U.S. PATENT DOCUMENTS

4,492,958	A	1/1985	Minami
4,550,221	A	10/1985	Mabusth
4,659,874	A	4/1987	Landmeier
4,667,259	A	5/1987	Uchida et al.
4,677,259	A	6/1987	Abe
4,705,919	A	11/1987	Dhawan
4,771,138	A	9/1988	Dhawan
4,878,013	A	10/1989	Andermo
4,954,823	A	9/1990	Binstead
4,999,462	A	3/1991	Purcell
5,053,715	A	10/1991	Andermo
5,062,916	A	11/1991	Aufderheide et al.
5,239,307	A	8/1993	Andermo
5,341,233	A	8/1994	Tomoike et al.
5,459,463	A	10/1995	Gruaz et al.
5,463,388	A	10/1995	Boie et al.
5,650,597	A	7/1997	Redmayne
5,657,012	A	8/1997	Tait
5,777,596	A	7/1998	Herbert
5,841,078	A	11/1998	Miller et al.
5,869,790	A	2/1999	Shigetaka et al.
6,188,391	B1	2/2001	Seely et al.
6,222,522	B1	4/2001	Mathews et al.
6,256,022	B1	7/2001	Manaresi et al.
6,281,888	B1	8/2001	Hoffman et al.
6,288,707	B1	9/2001	Philipp
6,297,811	B1	10/2001	Kent et al.
6,307,751	B1	10/2001	Bodony et al.
6,320,394	B1	11/2001	Tartagni
6,362,633	B1	3/2002	Tartagni
6,380,930	B1	4/2002	Van Ruymbeke
6,452,514	B1	9/2002	Philipp
6,459,044	B2	10/2002	Watanabe et al.
6,486,862	B1	11/2002	Jacobsen et al.
6,512,381	B2	1/2003	Kramer
6,535,200	B2	3/2003	Philipp
6,583,632	B2	6/2003	Von Basse et al.
6,653,736	B2	11/2003	Kishimoto et al.
6,731,120	B2	5/2004	Tartagni
6,771,327	B2	8/2004	Sekiguchi
6,825,833	B2	11/2004	Mulligan et al.
6,879,930	B2	4/2005	Sinclair et al.
6,910,634	B1	6/2005	Inose et al.
6,937,031	B2	8/2005	Yoshioka et al.
6,998,855	B2	2/2006	Tartagni
7,129,935	B2	10/2006	Mackey
7,158,125	B2	1/2007	Sinclair et al.
7,218,314	B2	5/2007	Itoh
7,306,144	B2	12/2007	Moore
7,327,352	B2	2/2008	Keefer et al.
7,339,579	B2	3/2008	Richter et al.
7,348,967	B2	3/2008	Zadesky et al.
7,382,139	B2	6/2008	Mackey
7,388,571	B2	6/2008	Lowles et al.
7,423,219	B2	9/2008	Kawaguchi et al.
7,423,635	B2	9/2008	Taylor et al.
7,439,962	B2	10/2008	Reynolds et al.
7,455,529	B2	11/2008	Fujii et al.
7,522,230	B2	4/2009	Lee
7,548,073	B2	6/2009	Mackey et al.
7,554,531	B2	6/2009	Baker et al.
7,589,713	B2	9/2009	Sato
7,663,607	B2	2/2010	Hotelling et al.
7,724,243	B2	5/2010	Geaghan
7,768,273	B1	8/2010	Kalnitsky et al.
7,786,981	B2	8/2010	Proctor
7,808,255	B2	10/2010	Hristov et al.
7,812,825	B2	10/2010	Sinclair et al.
7,821,274	B2	10/2010	Philipp et al.
7,821,502	B2	10/2010	Hristov
7,864,160	B2	1/2011	Geaghan et al.
7,876,309	B2	1/2011	XiaoPing
7,973,771	B2	7/2011	Geaghan
7,977,953	B2	7/2011	Lee
7,986,152	B2	7/2011	Philipp et al.
8,040,326	B2	10/2011	Hotelling et al.
8,059,015	B2	11/2011	Hua et al.
8,125,463	B2	2/2012	Hotelling et al.
8,243,027	B2	8/2012	Hotelling et al.
8,259,078	B2	9/2012	Hotelling et al.
8,278,571	B2	10/2012	Orsley
8,319,747	B2	11/2012	Hotelling et al.
2002/0077313	A1	6/2002	Clayman
2003/0052867	A1	3/2003	Shigetaka et al.
2003/0103043	A1	6/2003	Mulligan et al.
2003/0234771	A1	12/2003	Mulligan et al.
2004/0062012	A1	4/2004	Murohara
2004/0077313	A1	4/2004	Oba et al.
2004/0125087	A1	7/2004	Taylor et al.
2004/0222974	A1	11/2004	Hong et al.
2004/0239650	A1	12/2004	Mackey
2004/0252109	A1	12/2004	Trent et al.
2005/0030048	A1	2/2005	Bolender et al.
2006/0038754	A1	2/2006	Kim
2006/0097991	A1	5/2006	Hotelling et al.
2006/0114240	A1	6/2006	Lin
2006/0114241	A1	6/2006	Lin
2006/0232600	A1	10/2006	Kimura et al.
2007/0008299	A1	1/2007	Hristov
2007/0222762	A1	9/2007	Van Delden et al.
2007/0229466	A1	10/2007	Peng et al.
2007/0229468	A1	10/2007	Peng et al.
2007/0229469	A1	10/2007	Seguine
2007/0229470	A1	10/2007	Snyder et al.
2007/0242054	A1	10/2007	Chang et al.
2007/0257894	A1	11/2007	Philipp
2007/0262962	A1	11/2007	XiaoPing et al.
2007/0262963	A1	11/2007	Xiao-Ping et al.
2007/0268265	A1	11/2007	XiaoPing
2007/0273659	A1	11/2007	XiaoPing et al.
2007/0273660	A1	11/2007	XiaoPing
2007/0279395	A1	12/2007	Philipp et al.
2007/0291009	A1	12/2007	Wright et al.
2008/0006453	A1	1/2008	Hotelling
2008/0007534	A1	1/2008	Peng et al.
2008/0062140	A1	3/2008	Hotelling et al.
2008/0074398	A1	3/2008	Wright
2008/0111795	A1	5/2008	Bollinger
2008/0117182	A1	5/2008	Um et al.
2008/0150906	A1	6/2008	Grivna
2008/0158172	A1	7/2008	Hotelling et al.
2008/0158181	A1	7/2008	Hamblin et al.
2008/0164076	A1	7/2008	Orsley
2008/0218488	A1	9/2008	Yang et al.
2008/0245582	A1	10/2008	Bytheway
2008/0259044	A1	10/2008	Utsunomiya et al.
2008/0264699	A1	10/2008	Chang et al.
2008/0265914	A1	10/2008	Matsushima
2008/0297176	A1	12/2008	Douglas
2008/0308323	A1	12/2008	Huang et al.
2008/0309635	A1	12/2008	Matsuo
2009/0002337	A1	1/2009	Chang
2009/0002338	A1	1/2009	Kinoshita et al.
2009/0040191	A1	2/2009	Tong et al.
2009/0046077	A1	2/2009	Tanaka et al.
2009/0091551	A1	4/2009	Hotelling et al.
2009/0096757	A1	4/2009	Hotelling et al.
2009/0107737	A1	4/2009	Reynolds et al.
2009/0128518	A1	5/2009	Kinoshita et al.
2009/0135151	A1	5/2009	Sun
2009/0153509	A1	6/2009	Jiang et al.
2009/0160682	A1	6/2009	Bolender et al.
2009/0185100	A1	7/2009	Matsuhira et al.
2009/0201267	A1	8/2009	Akimoto et al.
2009/0207154	A1	8/2009	Chino
2009/0213082	A1	8/2009	Ku
2009/0213534	A1	8/2009	Sakai
2009/0236151	A1	9/2009	Yeh et al.
2009/0262096	A1	10/2009	Teramoto
2009/0267916	A1	10/2009	Hotelling
2009/0273571	A1	11/2009	Bowens
2009/0273573	A1	11/2009	Hotelling
2009/0277695	A1	11/2009	Liu et al.
2009/0283340	A1	11/2009	Liu et al.

(56) **References Cited**

U.S. PATENT DOCUMENTS

2009/0303203	A1	12/2009	Yilmaz et al.	
2009/0309850	A1	12/2009	Yang	
2009/0314621	A1	12/2009	Hotelling	
2009/0324621	A1	12/2009	Senter et al.	
2010/0001966	A1	1/2010	Lii et al.	
2010/0006347	A1	1/2010	Yang	
2010/0013745	A1	1/2010	Kim et al.	
2010/0013800	A1	1/2010	Elias et al.	
2010/0044122	A1	2/2010	Sleeman et al.	
2010/0090979	A1	4/2010	Bae	
2010/0134422	A1	6/2010	Borras	
2010/0140359	A1	6/2010	Hamm et al.	
2010/0147600	A1	6/2010	Orsley	
2010/0149108	A1*	6/2010	Hotelling et al.	345/173
2010/0156839	A1	6/2010	Ellis	
2010/0163394	A1	7/2010	Tang et al.	
2010/0182273	A1	7/2010	Noguchi et al.	
2010/0188359	A1	7/2010	Lee	
2010/0214247	A1	8/2010	Tang et al.	
2010/0220075	A1	9/2010	Kuo et al.	
2010/0258360	A1	10/2010	Yilmaz	
2010/0265210	A1	10/2010	Nakanishi et al.	
2010/0271330	A1	10/2010	Philipp	
2010/0277433	A1	11/2010	Lee et al.	
2010/0289770	A1	11/2010	Lee et al.	
2010/0291973	A1	11/2010	Nakahara et al.	
2010/0302201	A1	12/2010	Ritter et al.	
2010/0321043	A1	12/2010	Philipp et al.	
2010/0321326	A1	12/2010	Grunthaner et al.	
2011/0018841	A1	1/2011	Hristov	
2011/0022351	A1	1/2011	Philipp et al.	
2011/0025639	A1	2/2011	Trend et al.	
2011/0048812	A1	3/2011	Yilmaz	
2011/0048813	A1	3/2011	Yilmaz	
2011/0057887	A1	3/2011	Lin et al.	
2011/0062969	A1	3/2011	Hargreaves et al.	
2011/0062971	A1	3/2011	Badaye	
2011/0063251	A1	3/2011	Geaghan et al.	
2011/0080357	A1	4/2011	Park et al.	
2011/0090159	A1	4/2011	Kurashima	
2011/0096016	A1	4/2011	Yilmaz	
2011/0109579	A1	5/2011	Wang et al.	
2011/0109590	A1	5/2011	Park	
2011/0141051	A1	6/2011	Ryu	
2011/0169770	A1	7/2011	Mishina et al.	
2011/0187666	A1	8/2011	Min	
2011/0267300	A1	11/2011	Serban et al.	
2011/0273391	A1	11/2011	Bae	
2011/0279169	A1*	11/2011	Salaverry	327/517
2012/0044171	A1	2/2012	Lee et al.	
2012/0056820	A1	3/2012	Corbridge	
2012/0313901	A1	12/2012	Monson	

FOREIGN PATENT DOCUMENTS

EP	0810540	A2	12/1997
EP	0919945	A2	6/1999
EP	0977159	A1	2/2000
JP	2002215330	A	8/2002
JP	2002268768	A	9/2002
JP	2002268786	A	9/2002
JP	2011002947	A	1/2011
JP	2011002948	A	1/2011
JP	2011002949	A	1/2011
JP	2011002950	A	1/2011
JP	2011004076	A	1/2011
JP	2011100379	A	5/2011
KR	10110118065		10/2011
WO	86/06551	A1	11/1986
WO	0057344	A1	9/2000
WO	2010117946	A2	10/2010
WO	2010136932	A1	12/2010

OTHER PUBLICATIONS

Fujitsu Microelectronics Limited. "IC Package." (2002). 10 pages.
Quantum Research Group. "Qmatrix Technology White Paper", 2006. 4 pages.
Lubart, et al. "One Layer Optically Transparent Keyboard for Input Display", IP.com. Mar. 1, 1979. 3 Pages.
Gary L. Barrett et al. "Projected Capacitive Touch Screens", iTouchInternational. 9 pages.
Quantum Research Application Note an -KD01. "Qmatrix Panel Design Guidelines", Oct. 10, 2002. 4 Pages.
Calvin Wang et al. "Single Side All-Point-Addressable Clear Glass Substrate Sensor Design", IP.com. Apr. 2, 2009. 3 Pages.
Tsz-Kin Ho et al. "32.3: Simple Single-Layer Multi-Touch Projected Capacitive Touch Panel", SID 09 Digest.
Johannes Schoning et al. "Multi-Touch Surfaces: A Technical Guide", Technical Report TUM-10833. 2008.
Shawn Day. "Low Cost Touch Sensor on the Underside of a Casing", IP.com. Oct. 14, 2004.
Ken Gilleo. "The Circuit Centennial", 16 Pages.
Ken Gilleo, "The Definitive History of the Printed Circuit", 1999 PC Fab.
Hal Philipp. "Charge Transfer Sensing", vol. 19, No. 2. 1999. pp. 96-105.
Paul Leopardi, "A Partition of the Unit Sphere into Regions of Equal Area and Small Diameter", 2005.
Olivier Bau, "TeslaTouch: Electrovibration for Touch Surfaces", 2010.
Colin Holland. "SID: Single Layer Technology Boosts Capacitive Touchscreens", www.eetimes.com/General. 2011.
"Novel Single Layer Touchscreen Based on Indium", 2011.
"Mesh Patterns for Capacitive Touch or Proximity Sensors", IP.com. May 14, 2010. 3pages.
"IDT Claims World's First True Single-Layer Multi-Touch Projected Capacitive Touch Screen Technology", EE Times Europe. Dec. 8, 2010.
Tracy V. Wilson et al. "How the iPhone Works", HowStuffWorks "Multi-touch Systems". 2011.
Sunkook Kim et al. "A Highly Sensitive Capacitive Touch Sensor Integrated on a Thin-Film-Encapsulated Active-Matrix OLED for Ultrathin Displays", IEEE Transactions on Electron Devices, vol. 58, No. 10, Oct. 2011.
Mike Williams, "Dream Screens from Graphene", Technology Developed at Rice could Revolutionize Touch-Screen Displays. Aug. 2011.
ASIC Packaging Guidebook, Toshiba Corporation. (2000). 35 pages.

* cited by examiner

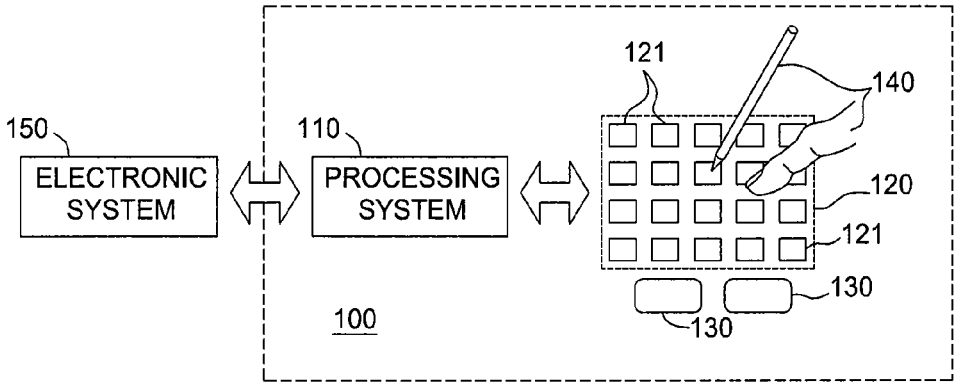

150
ELECTRONIC SYSTEM
110
PROCESSING SYSTEM
121
140
120
121
130
130
100

FIG. 1

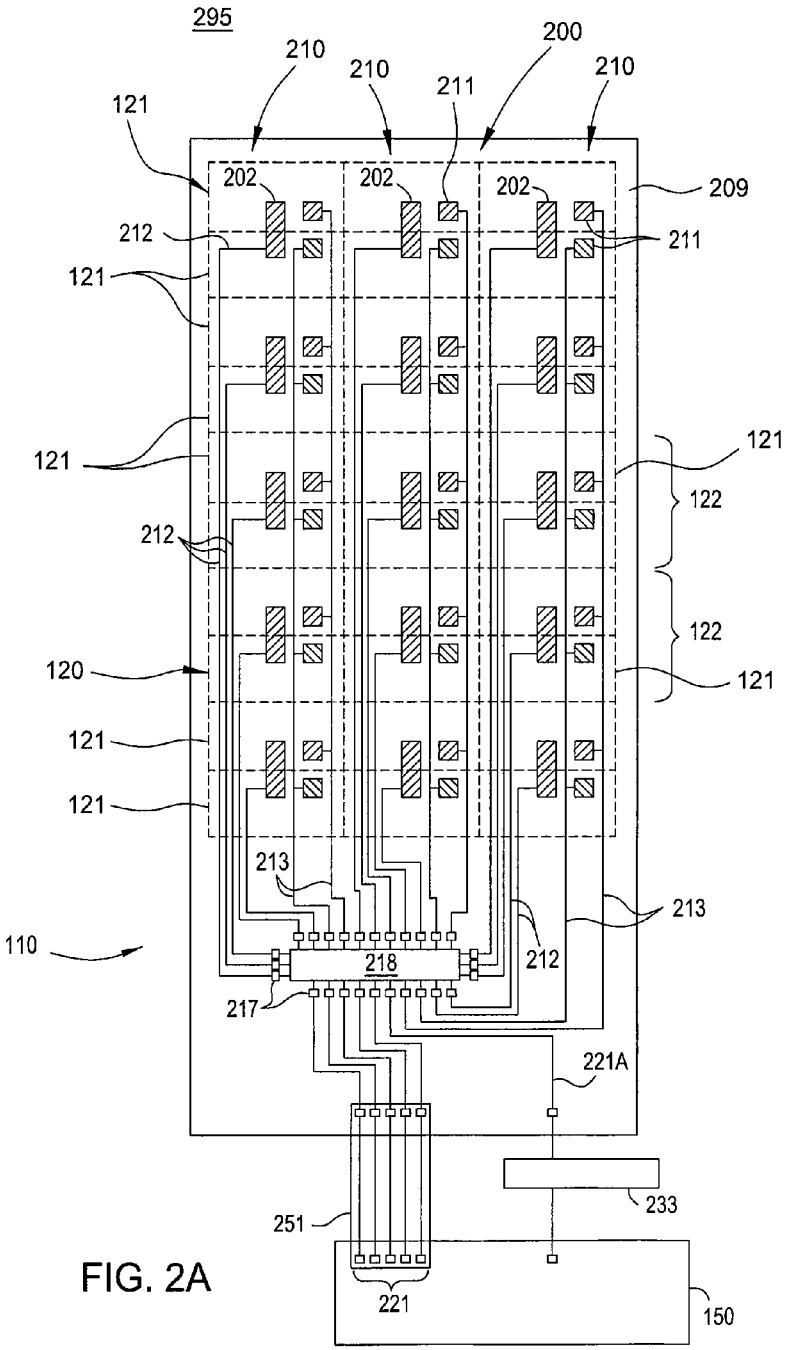

295
210
210
211
200
210
121
202
202
202
209
212
211
121
121
121
122
212
122
120
121
121
121
213
213
110
218
212
217
221A
233
251
221
150

FIG. 2A

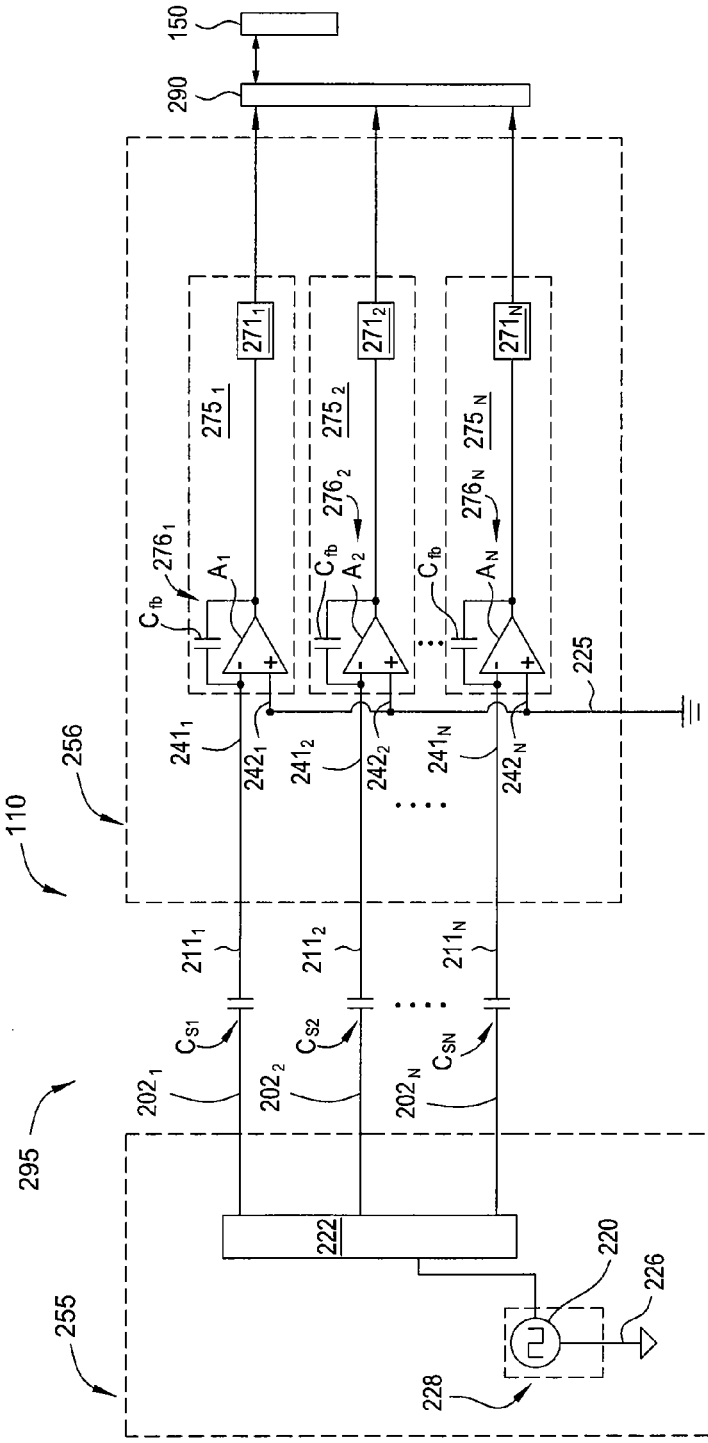

150
290
271 1
271 2
271 N
275 1
275 2
275 N
276 1
276 2
276 N
A1
A2
AN
Cfb
225
241 1
241 2
241 N
242 1
242 2
242 N
256
110
211 1
211 2
211 N
CS1
CS2
CSN
202 1
202 2
202 N
295
222
220
226
255
228

FIG. 2B

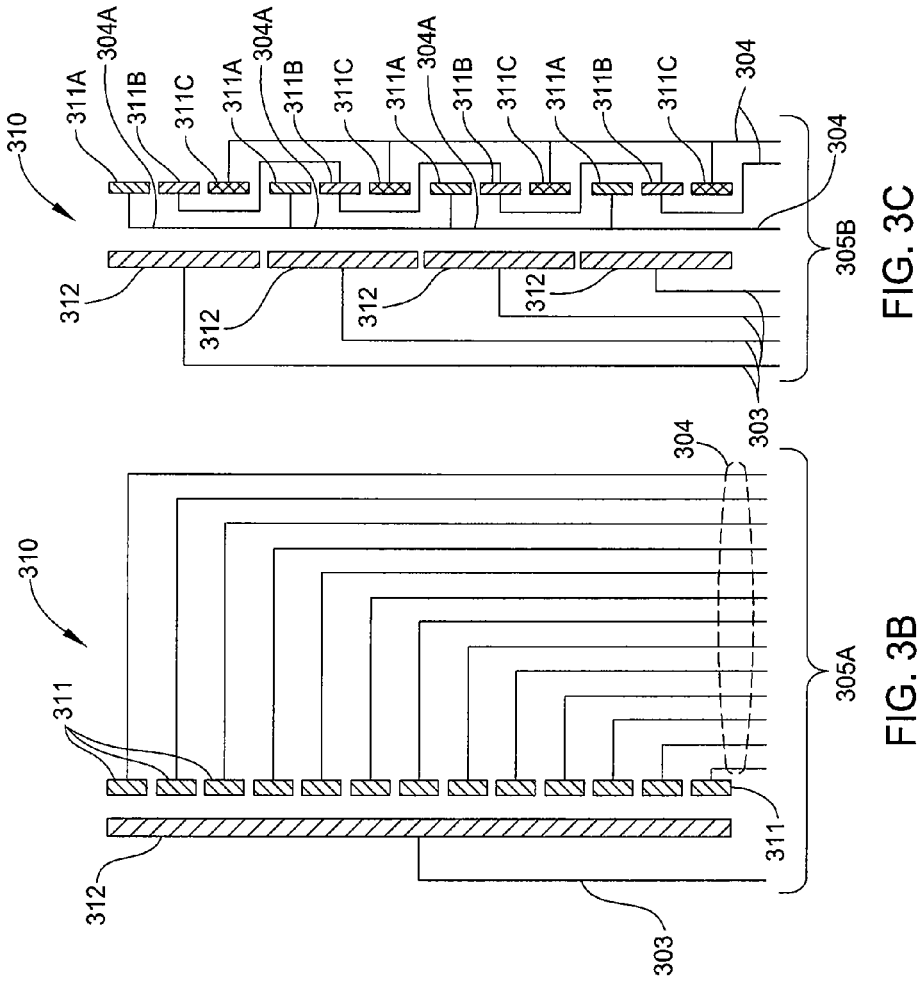


FIG. 3C

FIG. 3B

Transmitters (Tx)	Receivers (Rx)	Total
1	12	13
2	6	8
3	4	7
4	3	7
6	2	8
12	1	13

FIG. 3A

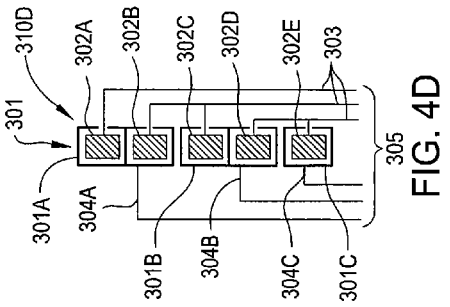


FIG. 4D

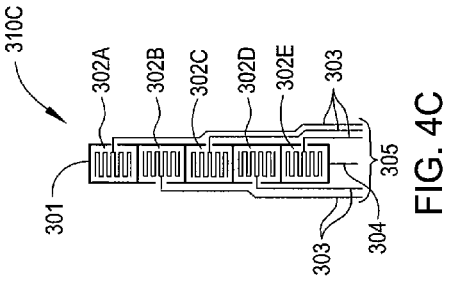


FIG. 4C

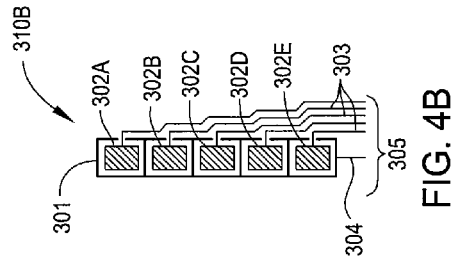


FIG. 4B

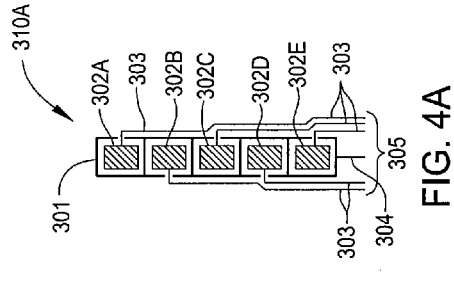


FIG. 4A

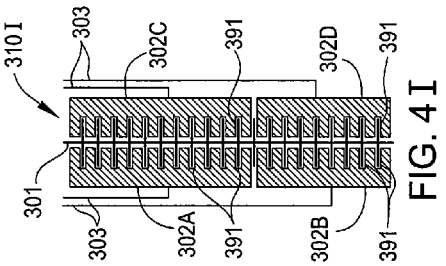


FIG. 4I

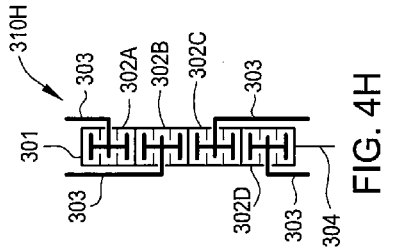


FIG. 4H

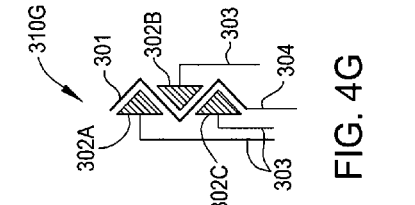


FIG. 4G

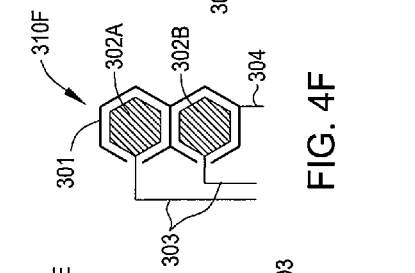


FIG. 4F

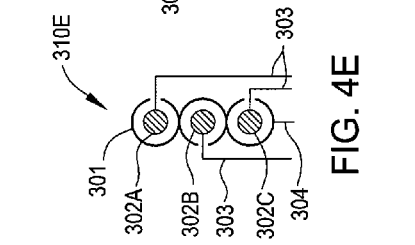


FIG. 4E

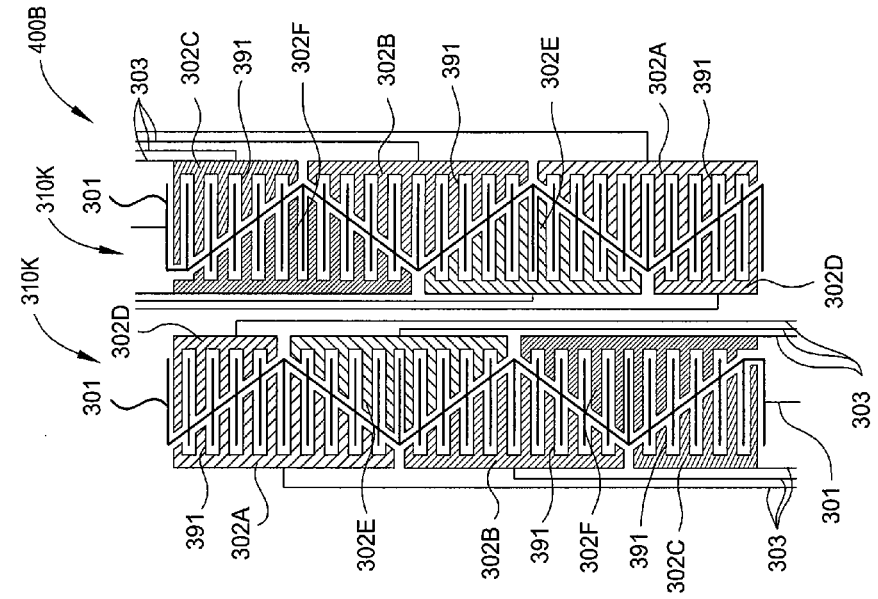

400B
303
302C
391
302F
302B
391
302E
302A
391
310K
301
310K
302D
301
391
302A
302E
302B
391
302F
391
302C
303
301
302D
303

FIG. 4K

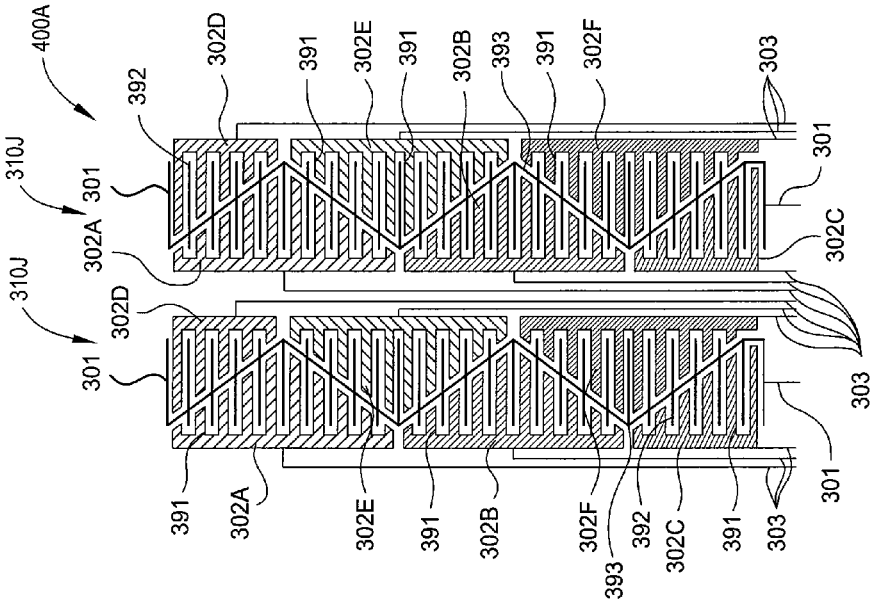

400A
392
302D
391
302E
391
302B
393
391
302F
303
310J
301
301
302A
302C
310J
302D
301
303
391
302A
302E
391
302B
302F
393
392
302C
391
303
301

FIG. 4J

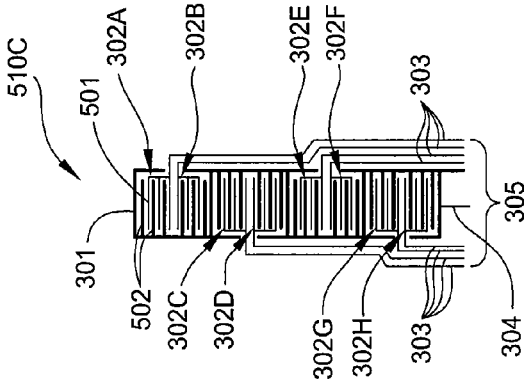


FIG. 5C

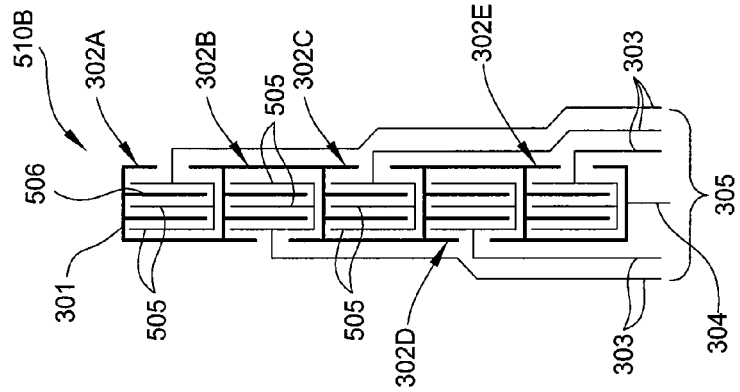


FIG. 5B

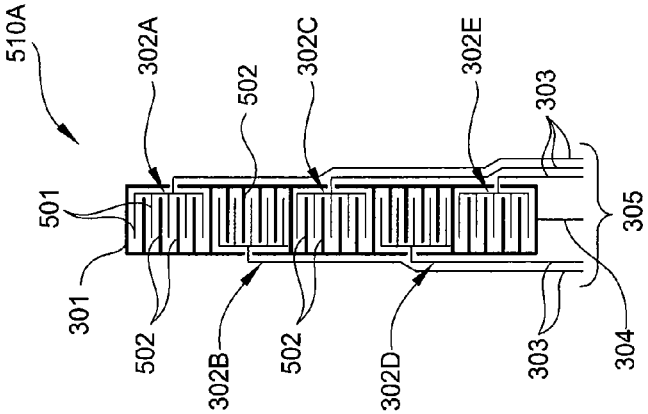


FIG. 5A

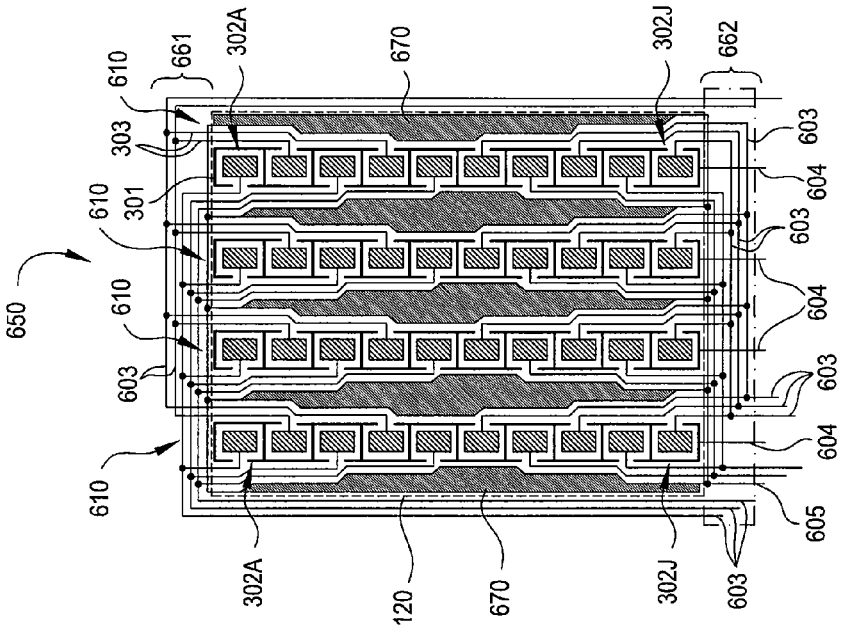

650
610
661
302A
670
302J
662
303
301
603
604
605
120

FIG. 6B

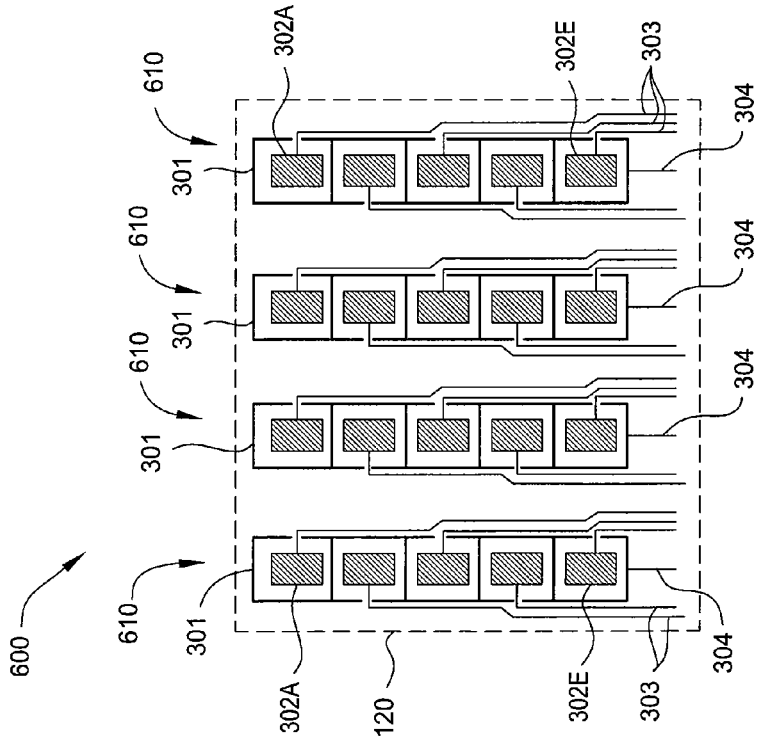

600
610
301
302A
302E
303
304
120

FIG. 6A

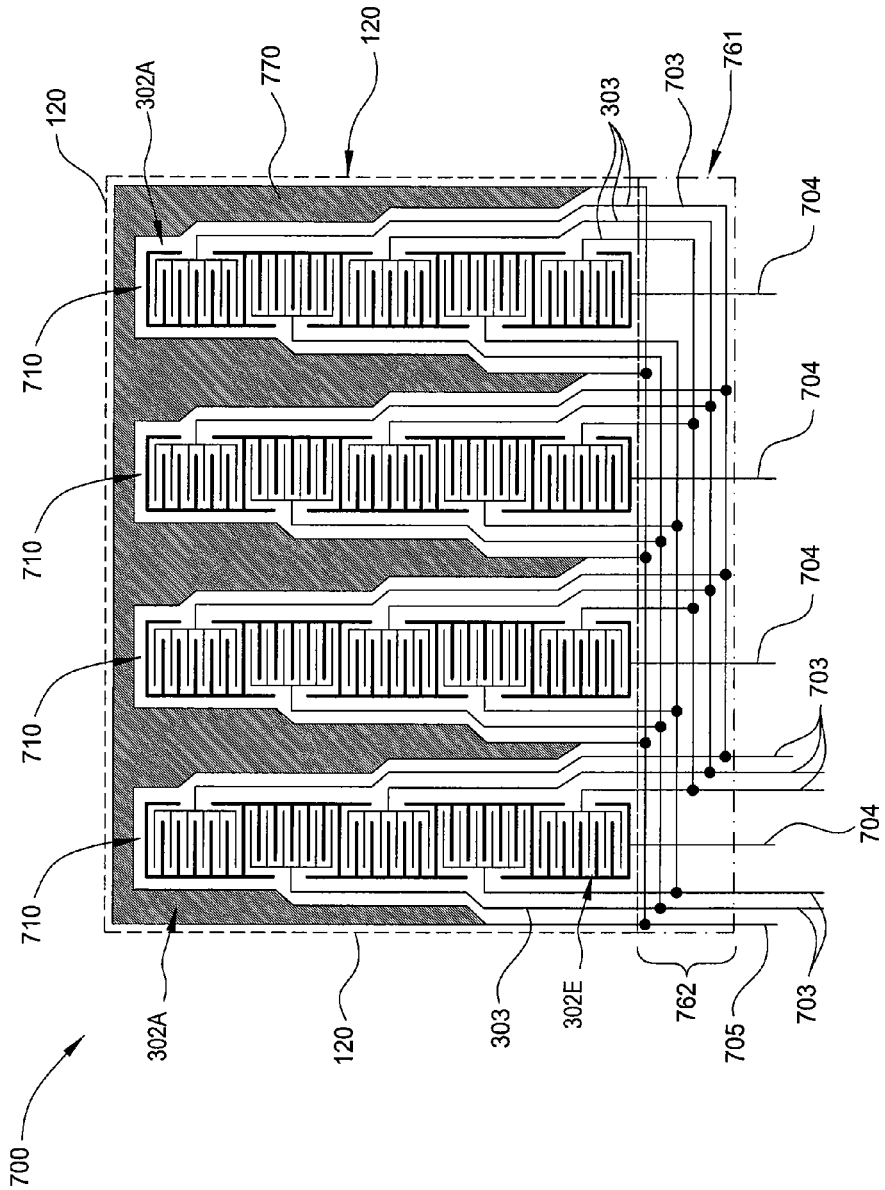

700
120
302A
770
120
303
703
761
704
710
704
710
704
710
703
704
710
302A
120
303
302E
762
705
703

FIG. 7

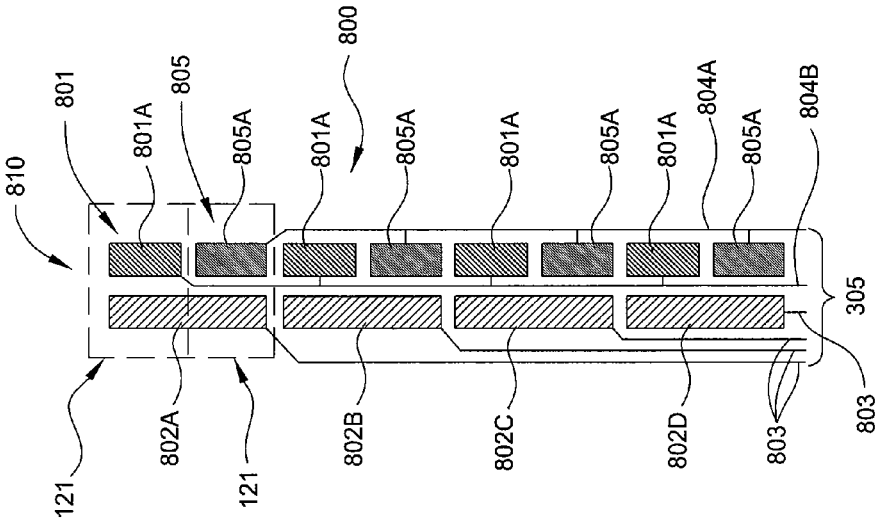

800
801
801A
805
805A
801A
805A
801A
805A
801A
804A
805A
804B
810
305
803
803
802A
802B
802C
802D
121
121

FIG. 8

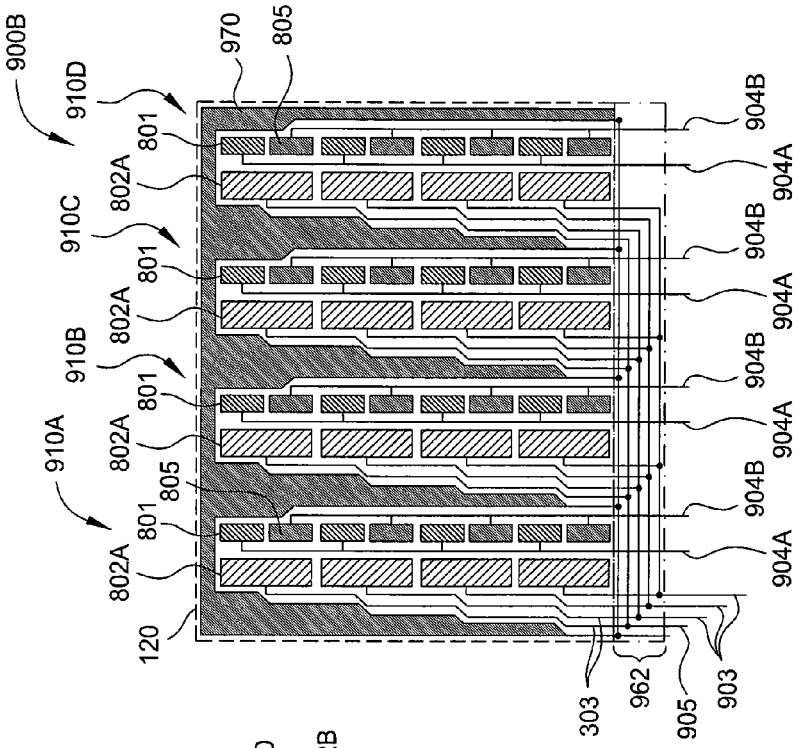

900B
910D
910C
910B
910A
970
805
801
802A
904B
904A
120
303
962
905
903

FIG. 9B

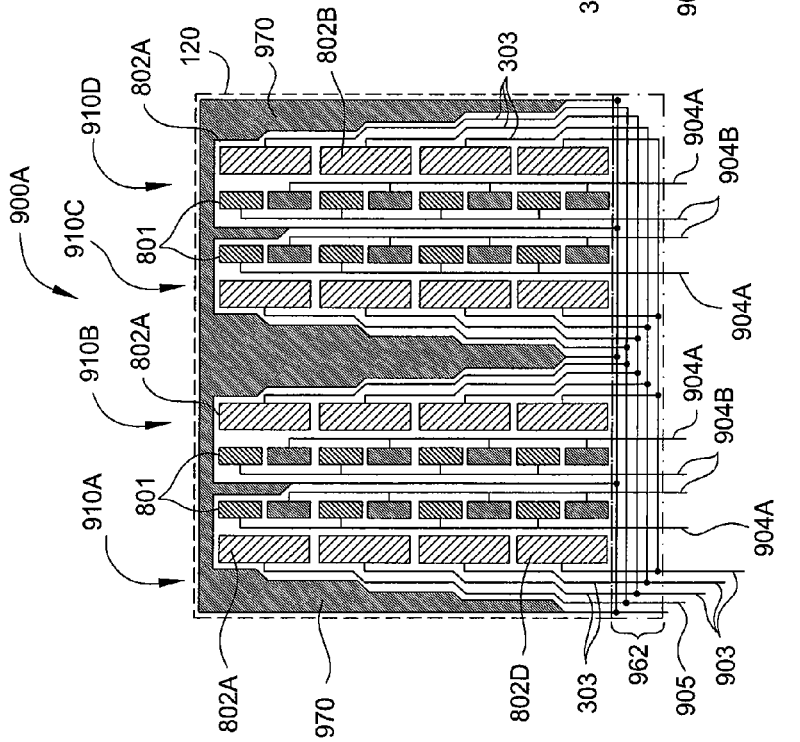

900A
910D
910C
910B
910A
120
970
802B
802A
801
904A
904B
303
802D
962
905
903

FIG. 9A

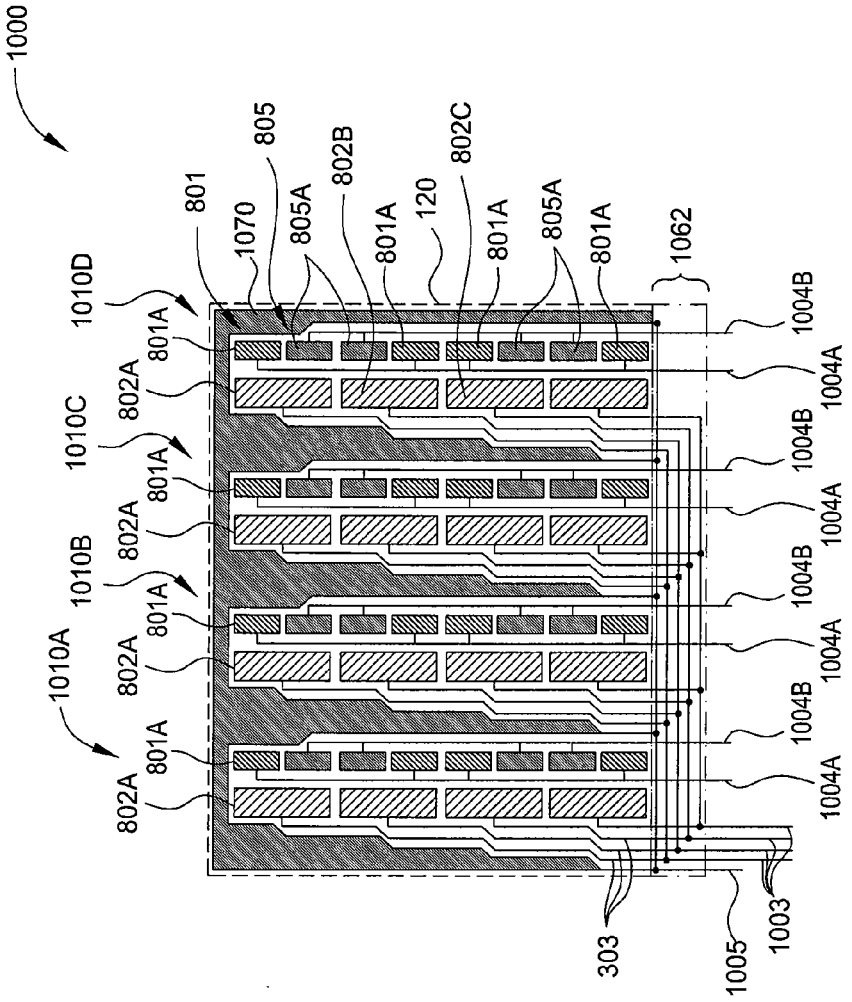

1000
801
1070
805
805A
802B
801A
120
802C
801A
805A
801A
1062
1010D
1010C
1010B
1010A
801A
802A
1004B
1004A
303
1005
1003

FIG. 10

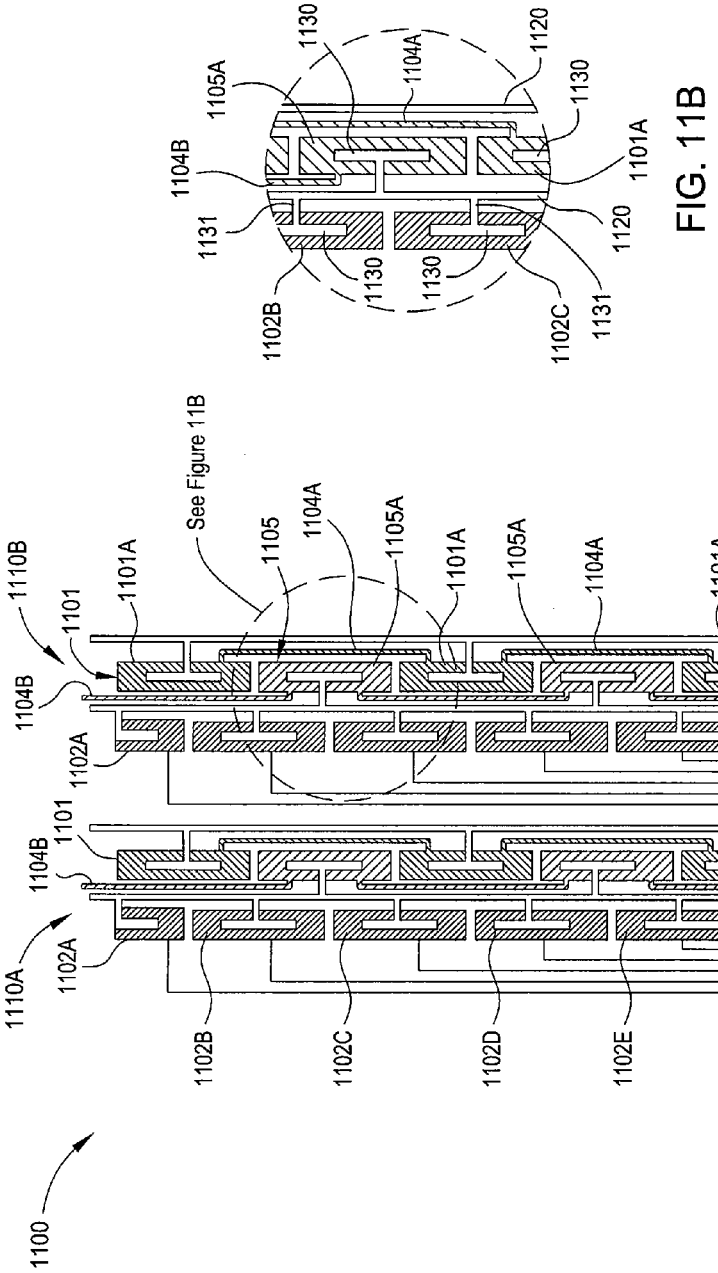


FIG. 11A

FIG. 11B

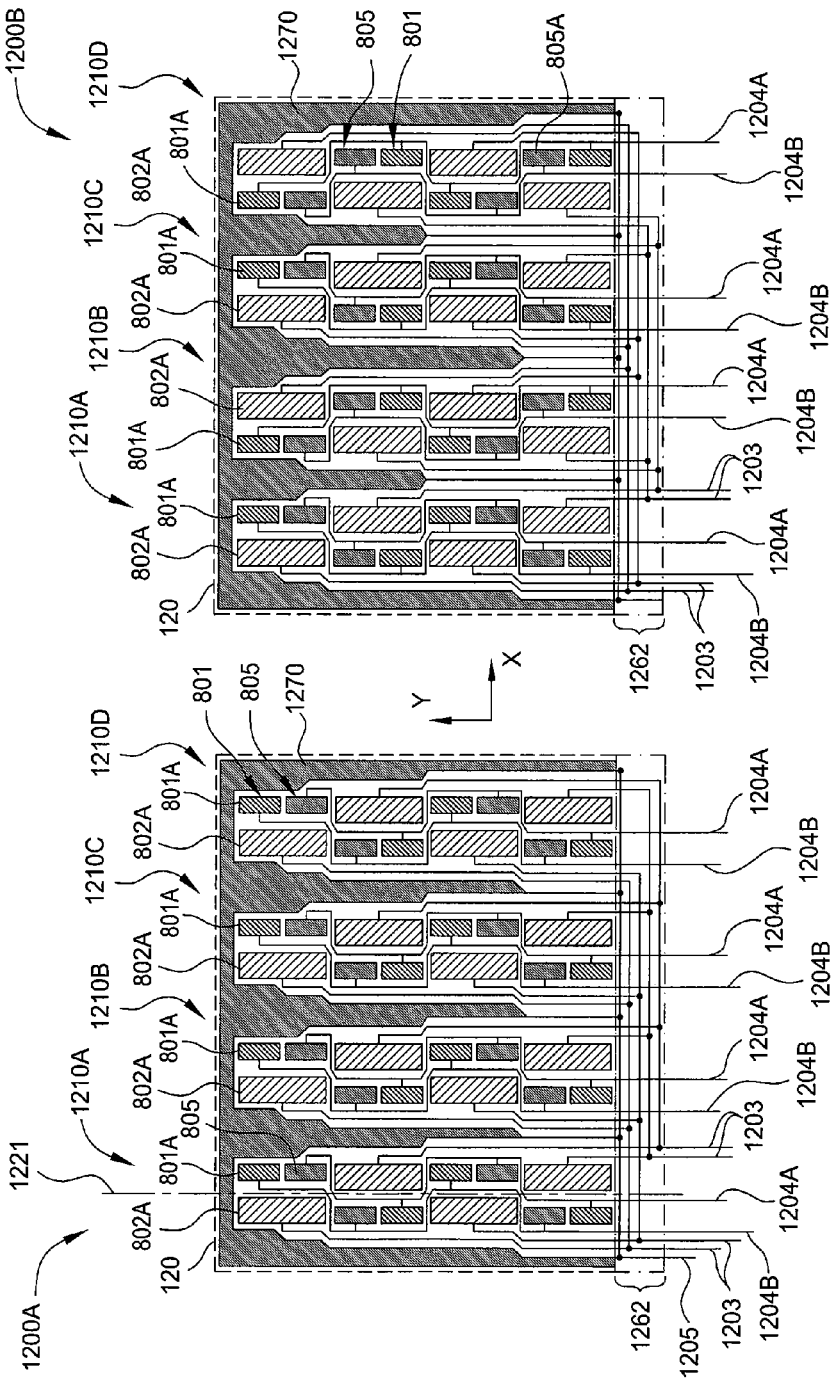


FIG. 12B

FIG. 12A

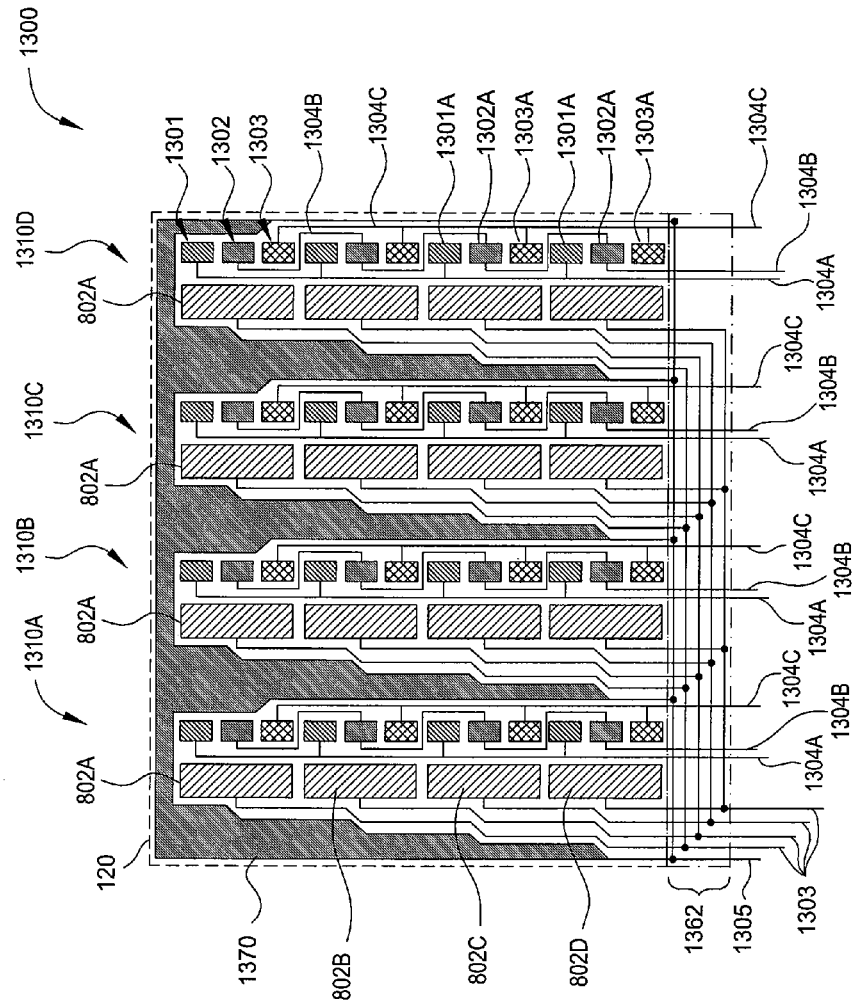

1300
1301
1302
1303
1304B
1304C
1301A
1302A
1303A
1301A
1302A
1303A
1304C
1304B
1310D
802A
1304A
1304C
1310C
1304B
802A
1304A
1310B
1304C
1304B
802A
1304A
1310A
1304C
1304B
802A
1304A
120
1370
802B
802C
802D
1362
1305
1303

FIG. 13

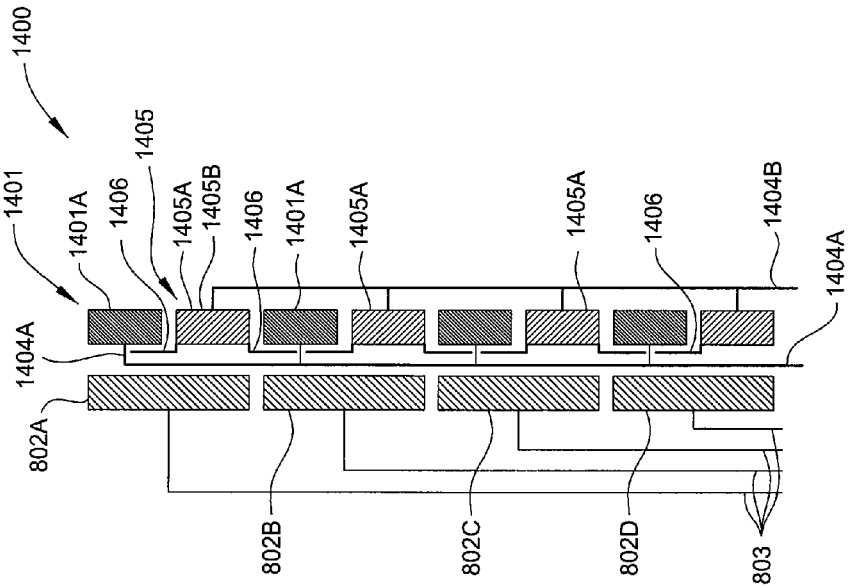

1400
1401
1401A
1406
1405
1405A
1405B
1406
1401A
1405A
1405A
1406
1404B
1404A
1404A
802A
802B
802C
802D
803

FIG. 14

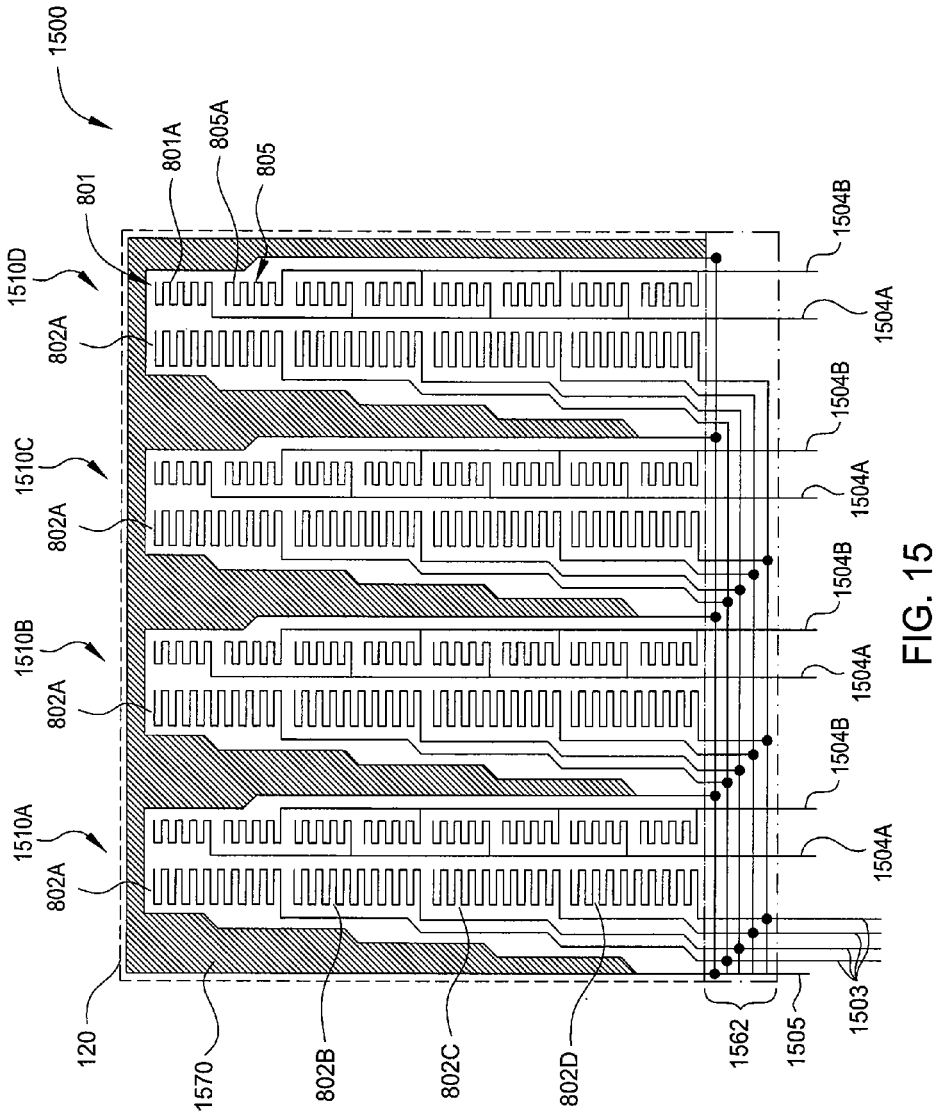

1500
801A
805A
805
801
1510D
802A
1510C
802A
1510B
802A
1510A
802A
1504B
1504A
1504B
1504A
1504B
1504A
1504B
1504A
120
1570
802B
802C
802D
1562
1505
1503

FIG. 15

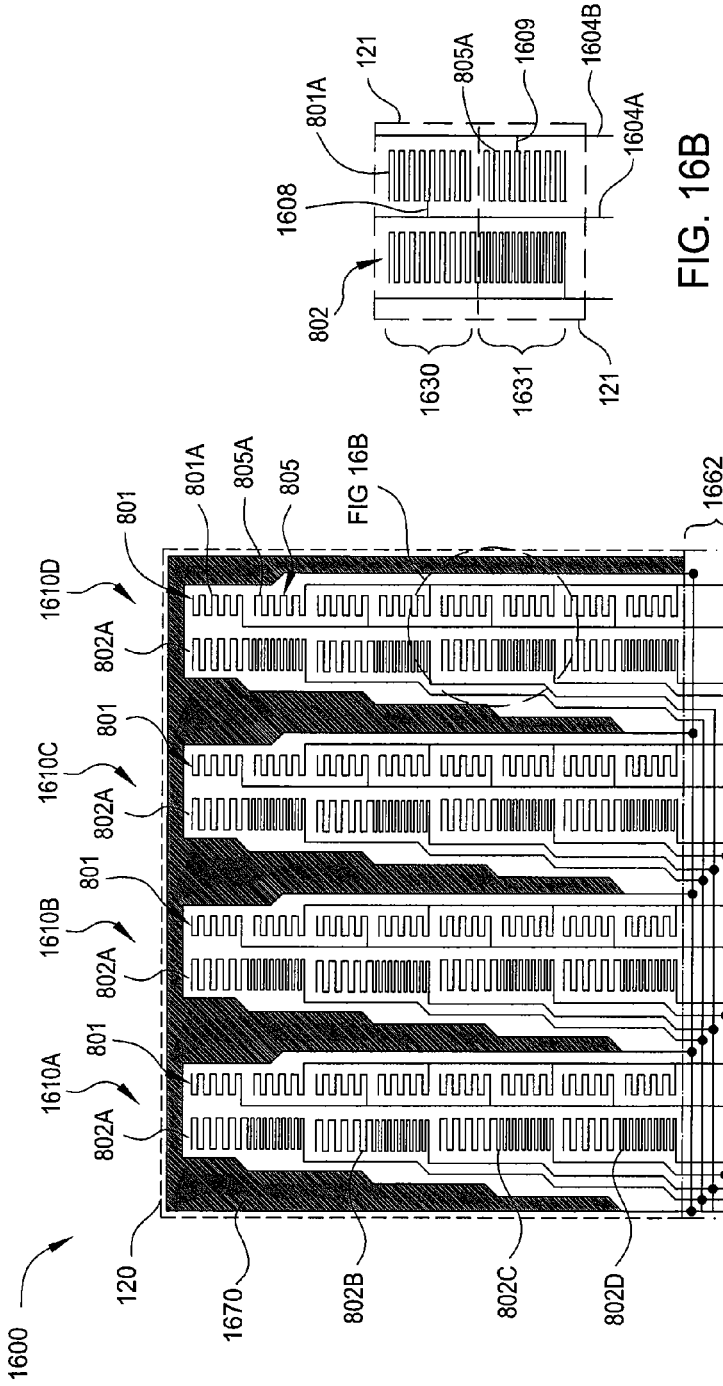


FIG. 16A

FIG. 16B

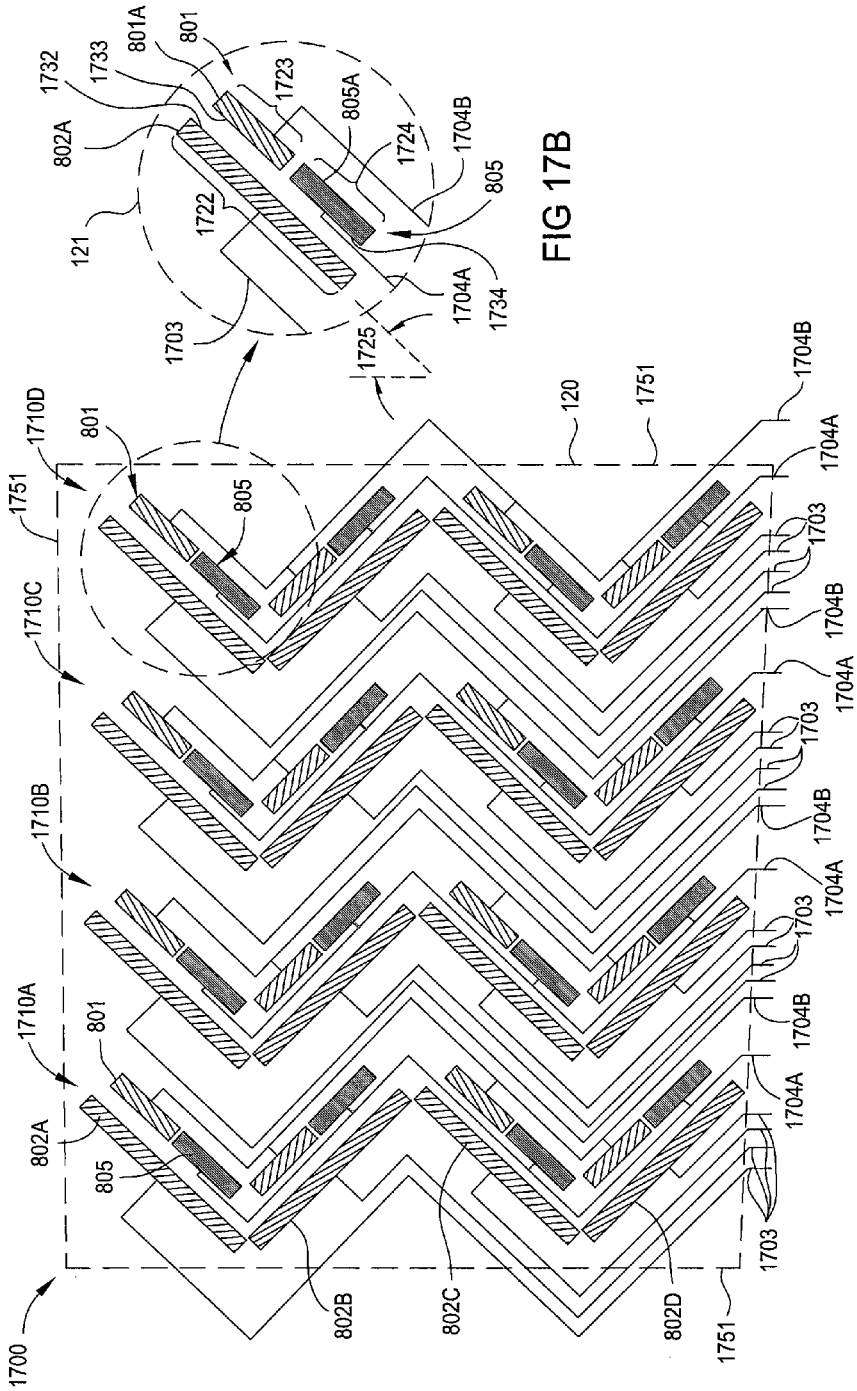


FIG 17B

FIG. 17A

SINGLE LAYER CAPACITIVE IMAGING SENSORS

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims benefit of U.S. provisional patent application Ser. No. 61/586,076, filed Jan. 12, 2012, which is herein incorporated by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

Embodiments of the present invention generally relate to a system and method for sensing an input object's position over a sensing region of a proximity sensing device.

2. Description of the Related Art

Input devices including proximity sensor devices, also commonly called touchpads or touch sensor devices, are widely used in a variety of electronic systems. A proximity sensor device typically includes a sensing region, often demarked by a surface, in which the proximity sensor device determines the presence, location and/or motion of one or more input objects. Proximity sensor devices may be used to provide interfaces for the electronic system. For example, proximity sensor devices are often used as input devices for larger computing systems, such as opaque touchpads integrated in, or peripheral to, notebook or desktop computers. Proximity sensor devices are also often used in smaller computing systems, such as touch screens integrated in cellular phones.

Proximity sensor devices are typically used in combination with other supporting components, such as display or input devices found in the electronic or computing system. In some configurations, the proximity sensor devices are coupled to these supporting components to provide a desired combined function or to provide a desirable complete device package. Many commercially available proximity sensor devices utilize one or more electrical techniques to determine the presence, location and/or motion of an input object, such as a capacitive or a resistive sensing technique. Typically, the proximity sensor devices utilize an array of sensor electrodes to detect the presence, location and/or motion of an input object. Due to the often large number of sensor electrodes used to sense the presence and position of an input object with desirable accuracy, and also the need to connect each of these sensor electrodes to the various signal generation and data collection components in the electronic or computing system, the cost associated with forming these interconnections, the reliability of the system and the overall size of the of the proximity sensor device are often undesirably large and complex. It is a common goal in the consumer and industrial electronics industries to reduce the cost and/or size of the electrical components in the formed electronic device. One will note that the cost and size limitations placed on the proximity sensor device are often created by the number of traces that are required, the number of required connection points, the connection component's complexity (e.g., number of pins on a connector) and the complexity of the flexible components used to interconnect the sensor electrodes to the control system.

Moreover, the greater the length of the traces used to interconnect the sensor electrodes to the computer system, the more susceptible the proximity sensor device is to interference, such as electromagnetic interference (EMI), commonly generated by the other supporting components. The interference provided by these supporting components will adversely affect the reliability and accuracy of the data collected by the proximity sensing device.

Therefore, there is a need for an apparatus and method of forming a proximity sensing device that is reliable, provides consistent and accurate position sensing results, is inexpensive to produce and can be integrated within a desirably sized electronic system.

SUMMARY OF THE INVENTION

Embodiments of the invention generally provide an input device having a reduced system complexity, smaller overall physical size and low production cost. The input device described herein can provide more reliable and accurate position sensing data and/or position sensing results based on the signals generated by the interaction of an input object with an input region of the input device. Embodiments of the invention generally provide an input device that uses arrays of sensor electrodes and/or sensor electrode interconnection schemes to form the position sensing data. Embodiments of the invention described herein thus provide an improved apparatus and method for reliably sensing the presence of an object by a touch sensing device. Also, one or more of the embodiments described herein, utilizes one or more of the techniques and electrode array configurations disclosed herein to reduce or minimize the number of traces and/or sensor electrodes required to sense the position of an input object within the sensing region.

Embodiments of the invention generally provide a capacitive image sensor that includes a first set of sensor electrodes and a second set of sensor electrodes. The first set of sensor electrodes includes a first sensor electrode, a second sensor electrode and a third sensor electrode. The first sensor electrode is electrically coupled to the third sensor electrode. The second set of sensor electrodes includes a fourth sensor electrode and a fifth sensor electrode, wherein the fourth sensor electrode is configured to capacitively couple with the first sensor electrode, and the fifth sensor electrode is configured to capacitively couple with the third sensor electrode.

Embodiments of the invention may further provide a capacitive image sensor that includes a first sensor electrode disposed on a first surface of a substrate, a second sensor electrode disposed on the first surface of the substrate, and a third sensor electrode disposed on the first surface of the substrate. The third sensor electrode is disposed between the first sensor electrode and the second sensor electrode, and is interdigitated with the first sensor electrode and interdigitated with the second sensor electrode.

Embodiments of the invention may further provide a touch screen that includes a sensor processor and a plurality of sensor electrodes disposed on a substrate, the plurality of sensor electrodes comprising a first sensor electrode disposed on a first surface of the substrate, a second sensor electrode disposed on the first surface of the substrate, and a third sensor electrode disposed on the first surface of the substrate. The third sensor electrode partially enclosing the first sensor electrode and partially enclosing the second sensor electrode, and at least a portion of the third sensor electrode is disposed between the first sensor electrode and the second sensor electrode. The sensor processor communicatively coupled to the first, second and third sensor electrodes, and configured to receive resulting signals received by the third sensor electrode when either the first or second sensor electrode is driven for capacitive sensing. The sensor processor further comprising a

first receiver channel coupled to the third receiver electrode, and wherein the first receiver channels comprises a charge accumulator.

Embodiments of the invention may further provide a capacitive image sensor that includes a first set of sensor electrodes and a second set of sensor electrodes. The first sensor electrode includes a first sensor electrode, a second sensor electrode and a third sensor electrode, and first sensor electrode is electrically coupled to the third sensor electrode. The second set of sensor electrodes comprising a fourth sensor electrode and a fifth sensor electrode, wherein the fourth sensor electrode is configured to capacitively couple with the first sensor electrode, and the fifth sensor electrode is configured to capacitively couple with the third sensor electrode.

Embodiments of the invention may further provide a touch screen that includes a plurality of sensor electrodes disposed on a surface of a transparent substrate, the plurality of sensor electrodes including a first set of sensor electrodes, a second set of sensor electrodes and a sensor processor. The first set of sensor electrodes include a first receiver electrode, a second receiver electrode and a third receiver electrode, and the first receiver electrode is electrically coupled to the third receiver electrode. The second set of sensor electrodes include a first transmitter electrode and a second transmitter electrode, wherein the first transmitter electrode is configured to capacitively couple with the first receiver electrode, and the second transmitter electrode is configured to capacitively couple with the third receiver electrode. The sensor processor communicatively coupled to the first and second receiver electrodes, and configured to receive resulting signals received by the first, second and third receiver electrodes when the first or second transmitter electrode is driven for capacitive sensing, wherein the sensor processor comprises a first receiver channel coupled to the first receiver electrode and a second receiver channel coupled to the second receiver electrode, and wherein the first and second receiver channels comprises a charge accumulator.

BRIEF DESCRIPTION OF THE DRAWINGS

So that the manner in which the above recited features of the present invention can be understood in detail, a more particular description of the invention, briefly summarized above, may be had by reference to embodiments, some of which are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only typical embodiments of this invention and are therefore not to be considered limiting of its scope, for the invention may admit to other equally effective embodiments.

FIG. **1** is a schematic block diagram of an exemplary input device, in accordance with embodiments of the invention.

FIG. **2**A is a schematic diagram illustrating an input device, according to one or more of the embodiments described herein.

FIG. **2**B is a schematic diagram illustrating a portion of an input device, according to one or more of the embodiments described herein.

FIG. **3**A is a table listing some examples of sensor electrode configurations that can be used in an input device, according to one or more of the embodiments described herein.

FIG. **3**B is a schematic diagram illustrating a sensor electrode configuration listed in the table shown in FIG. **3**A, according to one or more of the embodiments described herein.

FIG. **3**C is a schematic diagram illustrating a sensor electrode configuration listed in the table shown in FIG. **3**A, according to one or more of the embodiments described herein.

FIGS. **4**A-**4**K are each schematic diagrams illustrating a plurality of sensor electrodes that are positioned to form an array of sensor electrodes, according to one or more of the embodiments described herein.

FIGS. **5**A-**5**C are each schematic diagrams illustrating a plurality of sensor electrodes that are positioned to form an array of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **6**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **6**B is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **7** is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **8** is a schematic diagram illustrating a plurality of sensor electrodes that are positioned to form an array of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **9**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **9**B is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **10** is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **11**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **11**B is an enlarged schematic view of a portion of an array of sensor electrodes shown in FIG. **11**A, according to one or more of the embodiments described herein.

FIG. **12**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **12**B is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **13** is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **14** is a schematic diagram illustrating a plurality of sensor electrodes that are positioned to form an array of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **15** is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **16**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **16**B is an enlarged schematic view of a portion of an array of sensor electrodes shown in FIG. **16**A, according to one or more of the embodiments described herein.

FIG. **17**A is a schematic diagram illustrating a sensor electrode set that includes multiple arrays of sensor electrodes that each contain a plurality of sensor electrodes, according to one or more of the embodiments described herein.

FIG. **17**B is an enlarged schematic view of a portion of an array of sensor electrodes shown in FIG. **17**A, according to one or more of the embodiments described herein.

To facilitate understanding, identical reference numerals have been used, where possible, to designate identical elements that are common to the figures. It is contemplated that elements disclosed in one embodiment may be beneficially utilized on other embodiments without specific recitation. The drawings referred to here should not be understood as being drawn to scale unless specifically noted. Also, the drawings are often simplified and details or components omitted for clarity of presentation and explanation. The drawings and discussion serve to explain principles discussed below, where like designations denote like elements.

DETAILED DESCRIPTION

The following detailed description is merely exemplary in nature and is not intended to limit the invention or the application and uses of the invention. Furthermore, there is no intention to be bound by any expressed or implied theory presented in the preceding technical field, background, brief summary or the following detailed description.

Embodiments of the invention generally provide an input device having a reduced system complexity, small overall physical size and low production cost. One or more of the embodiments discussed herein comprise an input device that includes a plurality of sensing elements that are interconnected in desired way to reliably and accurately acquire positional information of an input object. The acquired positional information may be used to control the system's operation mode, as well as graphical user interface (GUI) actions, such as cursor movement, selection, menu navigation, and other functions. In one embodiment, one or more capacitive sensing techniques and/or novel sensor electrode array configurations are used to reduce or minimize the number of traces and/or sensor electrodes required to sense the positional information of an input object within the sensing region of the input device.

FIG. **1** is a block diagram of an exemplary input device **100**, in accordance with embodiments of the invention. In FIG. **1**, the input device **100** is a proximity sensor device (e.g., "touchpad," "touch screen," "touch sensor device") configured to sense inputs provided by one or more input objects **140** positioned in a sensing region **120**. Example input objects include fingers and styli, as shown in FIG. **1**. In some embodiments of the invention, the input device **100** may be configured to provide input to an electronic system **150**, which is sometime referred to herein as the "host." As used in this document, the term "electronic system" (or "electronic device") broadly refers to any system capable of electronically processing information. Some non-limiting examples of electronic systems include personal computers of all sizes and shapes, such as desktop computers, laptop computers, netbook computers, tablets, web browsers, e-book readers, and personal digital assistants (PDAs). Additional examples of electronic systems include composite input devices, such as physical keyboards that include input device **100** and separate joysticks or key switches. Further examples of electronic systems **150** include peripherals, such as data input devices (e.g., remote controls and mice) and data output devices (e.g., display screens and printers). Other examples include remote terminals, kiosks, video game machines (e.g., video game consoles, portable gaming devices, and the like), communication devices (e.g., cellular phones, such as smart phones), and media devices (e.g., recorders, editors, and players such as televisions, set-top boxes, music players, digital photo frames, and digital cameras). Additionally, the electronic system could be a host or a slave to the input device.

The input device **100** can be implemented as a physical part of the electronic system **150**, or can be physically separate from the electronic system. As appropriate, the input device **100** may communicate with parts of the electronic system **150** using any one or more of the following: buses, networks, and other wired or wireless interconnections. Examples include I^2C, SPI, PS/2, Universal Serial Bus (USB), Bluetooth, RF, and IRDA.

Sensing region **120** encompasses any space above, around, in and/or near the input device **100** in which the input device **100** is able to detect user input by one or more input objects **140**. The sizes, shapes, and locations of particular sensing regions may vary widely from embodiment to embodiment. In some embodiments, the sensing region **120** extends from a surface of the input device **100** in one or more directions into space until signal-to-noise ratios prevent sufficiently accurate object detection. The distance to which this sensing region **120** extends in a particular direction, in various embodiments, may be on the order of less than a millimeter, millimeters, centimeters, or more, and may vary significantly with the type of sensing technology used and the accuracy desired. Thus, some embodiments sense input that comprises no contact with any surfaces of the input device **100**, contact with an input surface (e.g., a touch surface) of the input device **100**, contact with an input surface of the input device **100** coupled with some amount of applied force or pressure, and/or a combination thereof. In various embodiments, input surfaces may be provided by surfaces of casings within which the sensor electrodes reside, by face sheets applied over the sensor electrodes or any casings, etc. In some embodiments, the sensing region **120** has a rectangular shape when projected onto an input surface of the input device **100**.

The input device **100** may utilize any combination of sensor components and sensing technologies to detect user input in the sensing region **120**. The input device **100** generally comprises one or more sensing elements **121** for detecting user input. As several non-limiting examples, the one or more sensing elements **121** in the input device **100** may use capacitive, elastive, resistive, inductive, magnetic acoustic, ultrasonic, and/or optical techniques to detect the position or motion of the input object(s) **140**. Some implementations are configured to provide sensing images that span one, two, three, or higher dimensional spaces.

In FIG. **1**, a processing system **110** is shown as part of the input device **100**. The processing system **110** is configured to operate the hardware of the input device **100** to detect input in the sensing region **120**. The processing system **110** comprises parts of or all of one or more integrated circuits (ICs) and/or other circuitry components. In some embodiments, the processing system **110** also comprises electronically-readable instructions, such as firmware code, software code, and/or the like. In some embodiments, components composing the processing system **110** are located together, such as near sensing element(s) **121** of the input device **100**. In other embodi-

ments, components of processing system **110** are physically separate with one or more components close to sensing elements **121** of input device **100**, and one or more components elsewhere. For example, the input device **100** may be a peripheral coupled to a desktop computer, and the processing system **110** may comprise software configured to run on a central processing unit of the desktop computer and one or more ICs (perhaps with associated firmware) separate from the central processing unit. As another example, the input device **100** may be physically integrated in a phone, and the processing system **110** may comprise circuits and firmware that are part of a main processor of the phone. In some embodiments, the processing system **110** is dedicated to implementing the input device **100**. In other embodiments, the processing system **110** also performs other functions, such as operating display screens, driving haptic actuators, etc.

The processing system **110** may be implemented as a set of modules that handle different functions of the input device **100**. Each module may comprise circuitry that is a part of the processing system **110**, firmware, software, or a combination thereof. In various embodiments, different combinations of modules may be used. In one example, modules include hardware operation modules for operating hardware such as sensing elements and display screens, data processing modules for processing data, such as sensor signals, and positional information, and reporting modules for reporting information. In another example, modules include sensor operation modules configured to operate sensing element(s) to detect input, identification modules configured to identify gestures such as mode changing gestures, and mode changing modules for changing operation modes.

In some embodiments, the processing system **110** responds to user input (or lack of user input) in the sensing region **120** directly by causing one or more actions. In one example, as noted above, actions may include changing operation modes, as well as GUI actions, such as cursor movement, selection, menu navigation, and other functions. In some embodiments, the processing system **110** provides information about the input (or lack of input) to some part of the electronic system (e.g., to a central processing system of the electronic system that is separate from the processing system **110**, if such a separate central processing system exists). In some embodiments, some part of the electronic system process information received from the processing system **110** is used to act on user input, such as to facilitate a full range of actions, including mode changing actions and GUI actions. For example, in some embodiments, the processing system **110** operates the sensing element(s) **121** of the input device **100** to produce electrical signals indicative of input (or lack of input) in the sensing region **120**. The processing system **110** may perform any appropriate amount of processing on the electrical signals in producing the information provided to the electronic system. For example, the processing system **110** may digitize analog electrical signals obtained from the sensing elements **121**. As another example, the processing system **110** may perform filtering or other signal conditioning. As yet another example, the processing system **110** may subtract or otherwise account for a baseline set of data (e.g., baseline image), such that the information reflects a difference between the acquired electrical signals (e.g., sensing image) and the baseline. As yet further examples, the processing system **110** may determine positional information, recognize inputs as commands, recognize handwriting, and the like.

"Positional information" as used herein broadly encompasses absolute position, relative position, velocity, acceleration, and other types of spatial information. Exemplary "zero-dimensional" positional information includes near/far or contact/no contact information. Exemplary "one-dimensional" positional information includes positions along an axis. Exemplary "two-dimensional" positional information includes motions in a plane. Exemplary "three-dimensional" positional information includes instantaneous or average velocities in space. Further examples include other representations of spatial information. Historical data regarding one or more types of positional information may also be determined and/or stored, including, for example, historical data that tracks position, motion, or instantaneous velocity over time.

In some embodiments, the input device **100** is implemented with additional input components that are operated by the processing system **110** or by some other processing system. These additional input components may provide redundant functionality for input in the sensing region **120**, or some other functionality. FIG. **1** shows buttons **130** near the sensing region **120** that can be used to facilitate selection of items using the input device **100**. Other types of additional input components include sliders, balls, wheels, switches, and the like. Conversely, in some embodiments, the input device **100** may be implemented with no other input components.

In some embodiments, the input device **100** comprises a touch screen interface, and the sensing region **120** overlaps at least part of an active area of a display screen of a display device (not shown). For example, the input device **100** may comprise substantially transparent sensor electrodes overlaying the display screen and provide a touch screen interface for the associated electronic system. The display screen may be any type of dynamic display capable of displaying a visual interface to a user, and may include any type of light emitting diode (LED), organic LED (OLED), cathode ray tube (CRT), liquid crystal display (LCD), plasma, electroluminescence (EL), or other display technology. The input device **100** and the display device may share physical elements. Some embodiments of the input device **100** include at least part of the display device. For example, some embodiments may utilize some of the same electrical components for displaying and sensing. In some examples, the display screen of the display device may be operated in part or in total by the processing system **110**.

It should be understood that while many embodiments of the present technology are described in the context of a fully functioning apparatus, the mechanisms of the present technology are capable of being distributed as a program product (e.g., software) in a variety of forms. For example, the mechanisms of the present technology may be implemented and distributed as a software program on information bearing media that are readable by electronic processors (e.g., non-transitory computer-readable and/or recordable/writable information bearing media readable by the processing system **110**). Additionally, the embodiments of the present technology apply equally regardless of the particular type of medium used to carry out the distribution. Examples of non-transitory, electronically readable media include various discs, memory sticks, memory cards, memory modules, and the like. Electronically readable media may be based on flash, optical, magnetic, holographic, or any other storage technology.

In many embodiments, the positional information of the input object **140** relative to the sensing region **120** is monitored or sensed by use of one or more sensing elements **121** (FIG. **1**) that are positioned to detect its "positional information." In general, the sensing elements **121** may comprise one or more sensing elements or components that are used to detect the presence of an input object. As discussed above, the one or more sensing elements **121** of the input device **100** may use capacitive, elastive, resistive, inductive, magnetic acous-

tic, ultrasonic, and/or optical techniques to sense the positional information of an input object. While the information presented below primarily discuses the operation of an input device **100**, which uses capacitive sensing techniques to monitor or determine the positional information of an input object **140** this configuration is not intended to be limiting as to the scope of the invention described herein, since other sensing techniques may be used.

In some resistive implementations of the input device **100**, a flexible and conductive first layer is separated by one or more spacer elements from a conductive second layer. During operation, one or more voltage gradients are created across the layers. Pressing the flexible first layer may deflect it sufficiently to create electrical contact between the layers, resulting in voltage outputs reflective of the point(s) of contact between the layers. These voltage outputs may be used to determine positional information.

In some inductive implementations of the input device **100**, one or more sensing elements pick up loop currents induced by a resonating coil or pair of coils. Some combination of the magnitude, phase, and frequency of the currents may then be used to determine positional information.

In one embodiment of the input device **100**, the sensing element **121** is a capacitive sensing element that is used to sense the positional information of the input object(s). In some capacitive implementations of the input device **100**, voltage or current is applied to the sensing elements to create an electric field between an electrode and ground. Nearby input objects **140** cause changes in the electric field, and produce detectable changes in capacitive coupling that may be detected as changes in voltage, current, or the like. Some capacitive implementations utilize arrays or other regular or irregular patterns of capacitive sensing elements to create electric fields. In some capacitive implementations, portions of separate sensing elements may be ohmically shorted together to form larger sensor electrodes. Some capacitive implementations utilize resistive sheets, which may be uniformly resistive.

Some capacitive implementations utilize "self capacitance" (or "absolute capacitance") sensing methods based on changes in the capacitive coupling between one or more sensing elements, or one or more sensor electrodes, and an input object. In various embodiments, an at least partially grounded input object positioned near the sensor electrodes alters the electric field near the sensor electrodes, thus changing the measured capacitive coupling of the sensor electrodes to ground. In one implementation, an absolute capacitance sensing method operates by modulating sensor electrodes with respect to a reference voltage (e.g., system ground), and by detecting the capacitive coupling between the sensor electrodes and the at least partially grounded input object(s).

Some capacitive implementations utilize "mutual capacitance" (or "transcapacitance") sensing methods based on changes in the capacitive coupling between two or more sensing elements (e.g., sensor electrodes). In various embodiments, an input object near the sensor electrodes alters the electric field created between the sensor electrodes, thus changing the measured capacitive coupling. In one implementation, a transcapacitive sensing method operates by detecting the capacitive coupling between one or more transmitter sensor electrodes (also "transmitter electrodes," "transmitting electrodes" or "transmitters") and one or more receiver sensor electrodes (also "receiver electrodes" or "receiving electrodes"). Transmitter sensor electrodes may be modulated relative to a reference voltage (e.g., system ground) to transmit transmitter signals. Receiver sensor electrodes may be held substantially constant relative to the reference voltage to facilitate receipt of "resulting signals." A "resulting signal" may comprise effect(s) corresponding to one or more transmitter signals, and/or to one or more sources of environmental interference (e.g., other electromagnetic signals). Sensor electrodes may be dedicated transmitters or receivers, or may be configured to both transmit and receive. In some implementations user input from an actively modulated device (e.g. an active pen) may act as a transmitter such that each of the sensor electrodes act as a receiver to determine the position of the actively modulated device.

Most conventional multi-touch sensing sensor devices, in which the location of more than one finger or other input can be accurately determined, comprise a matrix of transmitter sensor electrodes and receiver sensor electrodes. Conventionally, during operation, capacitive images are formed by measuring the capacitance formed between each transmitter and receiver sensor electrode (referred to as "transcapacitance" or "mutual capacitance"), forming a matrix or grid of capacitive detecting elements across the sensing region **120**. The presence of an input object (such as a finger or other object) at or near an intersection between transmitter and receiver sensor electrodes changes the measured "transcapacitance". These changes are localized to the location of object, where each transcapacitive measurement is a pixel of a "capacitive image" and multiple transcapacitive measurements can be utilized to form a capacitive image of the object.

Herein sensor design and sensing scheme embodiments are described that allow the creation of 2-D capacitance images using a single sensing layer in which all of the transmitting and receiving sensor electrodes are disposed in a single common layer with one another without the use of jumpers within the sensor area. The electronics to drive the sensor are located in a processing system, such as processing system **110** described herein. These described embodiments also facilitate contact sensing, proximity sensing, and position sensing. These described embodiments also facilitate "multi-touch" sensing, such as two finger rotation gestures and two finger pinch gestures, but with a less expensive sensor compared to a sensor that utilizes sensor electrodes in multiple layers. The reduced number of layers used to form the input device described herein versus other conventional position sensing devices also equates to fewer production steps, which in itself will reduce the production cost of the device. The reduction in the layers of the input device also decreases interference or obscuration of an image or display that is viewed through the sensor, thus lending itself to improved optical quality of the formed input device when it is integrated with a display device. Additional electrodes involved in sensing the shape of the electric fields of the transmitters and receivers, such as floating electrodes or shielding electrodes, may be included in the device and may be placed on other substrates or layers. The electrodes may be part of a display (share a substrate) and may even share functionality with the display (used for both display and sensing functionality). For example electrodes may be patterned in the Color filter of an LCD (Liquid Crystal Display) or on the sealing layer of an OLED (Organic Light Emitting Diode) display. Alternately, sensing electrodes within the display or on TFT (Thin Film Transistor) layer of an active matrix display may also be used as gate or source drivers. Such electrodes may be patterned (e.g. spaced or oriented at an angle relative to the pixels) such that they minimize any visual artifacts. Furthermore, they may use hiding layers (e.g. Black Mask between pixels) to hide at least some portion of one or more conductive electrodes.

FIG. **2**A is a schematic top view of a portion of an input device **295** that illustrates a portion of a sensor electrode pattern that may be used to sense the positional information of

an input object within the sensing region **120** using a transcapacitive sensing method. One will note that the input device **295** may be formed as part of a larger input device **100**, which is discussed above. In general, the sensor electrode pattern disclosed herein comprises a sensor array set **200** that includes a plurality of sensor electrode arrays **210** that include a plurality of sensor electrodes, such as sensor electrodes **202** and **211**, that are arranged and interconnected in a desirable manner to reduce or minimize the number of traces and/or sensor electrodes required to sense the positional information of an input object within the sensing region **120** of the input device **295**. For clarity of illustration and description, while FIG. **2**A illustrates a pattern of simple rectangles used to represent the sensor electrodes, this configuration is not meant to be limiting and in other embodiments, various other sensor electrode shapes may be used as discussed further herein. In other some embodiments, sensing elements **121** comprise two or more sensor electrodes, for example, sensor electrodes **202** and **211** that may be similar or different in size and/or shape. In one example, as shown, these sensor electrodes are disposed in a sensor electrode pattern that comprises a first plurality of sensor electrodes **202** (e.g., 15 shown) and a second plurality of sensor electrodes **211** (e.g., 30 shown), which are disposed on the same layer as the first plurality of sensor electrodes **202**. Sensor electrodes **202** and sensor electrodes **211** are typically ohmically isolated from each other, by use of insulating materials or a physical gap formed between the electrodes to prevent them from electrically shorting to each other. In some configurations, two or more sensing elements **121** may form a larger unit cell **122**. A unit cell **122** includes a grouping of sensor electrodes that are repeated within a sensor electrode array **210** and/or in a repeating pattern across the sensing region **120** (e.g., multiple sensor electrode arrays **210**). The unit cell **122** is the smallest unit a symmetric grouping of sensor electrodes can be broken into within an electrode pattern formed across the sensing region **120**. As illustrated in FIG. **2**A, in one example, the unit cell **122** includes two sensing elements **121**, which each contain a portion of the sensor electrode **202** and the sensor electrode **211**, and thus the unit cell **122** comprises a sensor electrode **202** and two sensor electrodes **211**. One will note that the sensor electrode pattern of FIG. **2**A may alternatively utilize various sensing techniques, such as mutual capacitive sensing, absolute capacitive sensing, elastive, resistive, inductive, magnetic acoustic, ultrasonic, or other useful sensing techniques, without deviating from the scope of the invention described herein. Sensor electrode **202** maybe be a transmitter and **211** maybe a receiver, or vice versa (the other way around) with typically similar imaging capability.

In one embodiment, as illustrated in FIG. **2**A, the sensing elements **121** may comprise a plurality of transmitter and receiver electrodes that are formed in a single layer on a surface of a substrate **209**. In one configuration of the input device **295**, each of the sensor electrodes may comprise one or more transmitter electrodes (e.g. sensor electrodes **202**) that are disposed proximate to one or more receiver electrodes (e.g. sensor electrodes **211**). In one example, a transcapacitive sensing method using the single layer sensor electrode design, may operate by detecting the change in capacitive coupling between one or more of the driven transmitter sensor electrodes and one or more of the receiver electrodes, as similarly discussed above. In such embodiments, the transmitter and receiver electrodes may be disposed in such a way such that jumpers and/or extra layers used to form the area of capacitive pixels are not required. In various embodiments, the transmitter electrodes and receiver electrodes may be formed in an array on the surface of a substrate **209** by first forming a blanket conductive layer on the surface of the substrate **209** and then performing an etching and/or patterning process (e.g., lithography and wet etch, laser ablation, etc.) that ohmically isolates each of the transmitter electrodes and receiver electrodes from each other. In other embodiments, the sensor electrodes may be patterned using deposition and screen printing methods. As illustrated in FIG. **2**A, these sensor electrodes may be disposed in an array that comprises a rectangular pattern of sensing elements **121**, which may comprise one or more transmitter electrodes and one or more receiver electrodes. In one example, the blanket conductive layer used to form the transmitter electrodes and receiver electrodes comprises a thin metal layer (e.g., copper, aluminum, etc.) or a thin transparent conductive oxide layer (e.g., ATO, ITO, Zinc oxide) that is deposited using convention deposition techniques known in the art (e.g., PVD, CVD). In various embodiments, patterned isolated conductive electrodes (e.g., electrically floating electrodes) may be used to improve visual appearance. In one or more of the embodiments described herein, the sensor electrodes are formed from a material that is substantially optically clear, and thus, in some configurations, can be disposed between a display device and the input device user.

The areas of localized capacitive coupling formed between at least a portion of one or more sensor electrodes **202** and at least a portion of one or more sensor electrodes **211** may be termed a "capacitive pixel," or also referred to herein as the sensing element **121**. For example, as shown in FIG. **2**A, the capacitive coupling in a sensing element **121** may be created by the electric field formed between at least a portion of the sensor electrodes **202** and a sensor electrode **211**, which changes as the proximity and motion of input objects across the sensing region changes.

In some embodiments, the sensing elements **121** are "scanned" to determine these capacitive couplings. The input device **295** may be operated such that one transmitter electrode transmits at one time, or multiple transmitter electrodes transmit at the same time. Where multiple transmitter electrodes transmit simultaneously, these multiple transmitter electrodes may transmit the same transmitter signal and effectively produce an effectively larger transmitter electrode, or these multiple transmitter electrodes may transmit different transmitter signals. In one example, the transmitter electrodes are the sensor electrodes **202** and the receiver electrodes are the sensor electrodes **211**. For example, in one configuration, multiple sensor electrodes **202** transmit different transmitter signals according to one or more coding schemes that enable their combined effects on the resulting signals received by the receiving sensor electrodes, or sensor electrodes **211**, to be independently determined. The direct effect of a user input which is coupled to the device may affect (e.g. reduce the fringing coupling) of the resulting signals. Alternately, a floating electrode may be coupled to the input and to the transmitter and receiver and the user input may lower its impedance to system ground and thus reduce the resulting signals. In a further example, a floating electrode may be displaced toward the transmitter and receiver which increases their relative coupling. The receiver electrodes, or a corresponding sensor electrode **211**, may be operated singly or multiply to acquire resulting signals created from the transmitter signal. The resulting signals may be used to determine measurements of the capacitive couplings at the capacitive pixels, which are used to determine whether an input object is present and its positional information, as discussed above. A set of values for the capacitive pixels form a "capacitive image" (also "capacitive frame" or "sensing image") representative of the capacitive couplings at the pixels. In various

embodiments, the sensing image, or capacitive image, comprises data received during a process of measuring the resulting signals received with at least a portion of the sensing elements **121** distributed across the sensing region **120**. The resulting signals may be received at one instant in time, or by scanning the rows and/or columns of sensing elements distributed across the sensing region **120** in a raster scanning pattern (e.g., serially polling each sensing element separately in a desired scanning pattern), row-by-row scanning pattern, column-by-column scanning pattern or other useful scanning technique. In many embodiments, the rate that the "sensing image" is acquired by the input device **100**, or sensing frame rate, is between about 60 and about 180 Hertz (Hz), but can be higher or lower depending on the desired application.

In some touch screen embodiments, the sensing elements **121** are disposed on a substrate of an associated display device. For example, the sensor electrodes **202** and/or the sensor electrodes **211** may be disposed on a polarizer, a color filter substrate, or a glass sheet of an LCD. As a specific example, the sensor electrodes **202** and **211** may be disposed on a TFT (Thin Film Transistor) substrate of an LCD type of the display device, a color filter substrate, on a protection material disposed over the LCD glass sheet, on a lens glass (or window), and the like. The electrodes may be separate from and in addition to the display electrodes, or shared in functionality with the display electrodes. Similarly, an extra layer may be added to a display substrate or an additional process such as patterning applied to an existing layer.

In some touchpad embodiments, the sensing elements **121** are disposed on a substrate of a touchpad. In such an embodiment, the sensor electrodes in each sensing element **121** and/or the substrate may be substantially opaque. In some embodiments, the substrate and/or the sensor electrodes of the sensing elements **121** may comprise a substantially transparent material.

In those embodiments, where sensor electrodes of each of the sensing elements **121** are disposed on a substrate within the display device (e.g., color filter glass, TFT glass, etc.), the sensor electrodes may be comprised of a substantially transparent material (e.g., ATO, ClearOhm™) or they may be comprised of an opaque material and aligned with the pixels of the display device. Electrodes may be considered substantially transparent in a display device if their reflection (and/or absorption) of light impinging on the display is such that human visual acuity is not disturbed by their presence. This may be achieved by matching indexes of refraction, making opaque lines narrower, reducing fill percentage or making the percentage of material more uniform, reducing spatial patterns (e.g. moire') that are with human visible perception, and the like.

In one configuration, as illustrated in FIG. **2**A and further discussed below, the processing system **110** of the input device **295** comprises a sensor controller **218** that is coupled through connectors **217** to each of the transmitter and receiver electrodes, such as sensor electrodes **202** and **211**, through one or more traces (e.g., traces **212** and **213**) respectively. In one embodiment, the sensor controller **218** is generally configured to transmit the transmitter signal and receive the resulting signals from receiver electrodes. The sensor controller **218** is also generally configured to communicate the positional information received by the sensing elements **121** to the electronic system **150** and/or the display controller **233**, which is also coupled to the electronic system **150**. The sensor controller **218** may be coupled to the electronic system **150** using one or more traces **221** that may pass through a flexible element **251** and be coupled to the display controller **233** using one or more traces **221**A that may pass through the same flexible element **251** or a different connecting element, as shown. While the processing system **110** illustrated in FIG. **2**A schematically illustrates a single component (e.g., IC device) to form the sensor controller **218**, the sensor controller **218** may comprise two or more controlling elements (e.g., IC devices) to control the various components in the processing system **110** of the input device **295**. The controller devices may be placed onto display substrates such as TFT or Color Filter/Sealing layers (e.g. as a Chip On Glass).

In one configuration, the functions of the sensor controller **218** and the display controller **233** may be implemented in one integrated circuit that can control the display module elements and drive and/or sense data delivered to and/or received from the sensor electrodes. In various embodiments, calculation and interpretation of the measurement of the resulting signals may take place within the sensor controller **218**, display controller **233**, a host electronic system **150**, or some combination of the above. In some configurations, the processing system **110** may comprise a transmitter circuitry, receiver circuitry, and memory that is disposed within one or any number of ICs found in the processing system **110**, depending to the desired system architecture.

FIG. **2**B is a schematic view of a portion of the processing system **110** of the input device **295** according to one or more of the embodiments described herein. In one configuration, the sensor controller **218** includes a signal generating processor **255** and sensor processor **256** that work together to provide touch sensing data to an analysis module **290** and the electronic system **150**. The analysis module **290** may be part of the processing system **110**, the sensor processor **256** and/or part of the electronic system **150**. In various embodiments, the analysis module **290** will comprises digital signal processing elements and/or other useful digital and analog circuit elements that are connected together to process the receiver channel output signal(s) received from at least one receiver channel that is coupled to a receiver electrode, and also provide processed signals to other portions of the electronic system **150**. The electronic system **150** can then use the processed signals to control some aspect of the input device **295**, such as send a message to the display, perform some calculation or software related task based on instructions created by one or more software programs that are being run by the electronic system and/or perform some other function.

As illustrated in FIG. **2**B, the processing system **110** may comprise a signal generating processor **255** and a sensor processor **256** that work together to provide receiver channel output signals to the analysis module **290** and/or the electronic system **150**. As discussed above, the positional information of an input object **140** (FIG. **1**) is derived based on the capacitance C_s (e.g., capacitance C_{S1}, C_{S2}, C_{SN}) measured between each of the transmitter electrodes (e.g., sensor electrodes $\mathbf{202}_1$, $\mathbf{202}_2$, . . . $\mathbf{202}_N$) and the receiver electrodes (e.g., sensor electrodes $\mathbf{211}_1$, $\mathbf{211}_2$, . . . $\mathbf{211}_N$).

In one embodiment, as shown in FIG. **2**B, the signal generating processor **255** comprises a driver **228**, which are adapted to deliver capacitive sensing signals (transmitter signals) to the transmitter electrodes. In one configuration, the driver **228** may comprise a power supply and signal generator **220** that is configured to deliver a square, rectangular, trapezoidal, sinusoidal, Gaussian or other shaped waveforms used to form the transmitter signal(s) to the transmitter electrodes. In one configuration, the signal generator **220** comprises an electrical device, or simple switch, that is able to deliver a transmitter signal that transitions between the output level of the power supply and a low display voltage level. In various embodiments, signal generator **220** may comprise an oscillator. In some configurations, the signal generator **220** is

integrated into the driver **222**, which includes one or more shift registers (not shown) and/or switches (not shown) that are adapted to sequentially deliver transmitter signals to one or more of the transmitter electrodes at a time.

In one embodiment, as shown in FIG. **2**B, the sensor processor **256** comprises a plurality of receiver channels **275** (e.g., receiver channels $\mathbf{275}_1$, $\mathbf{275}_2$, . . . $\mathbf{275}_N$) that each have a first input port **241** (e.g., ports $\mathbf{241}_1$, $\mathbf{241}_2$, . . . $\mathbf{241}_N$) that is configured to receive the resulting signal received with at least one receiver electrode (e.g., sensor electrode $\mathbf{211}_1$, $\mathbf{211}_2$, . . . $\mathbf{211}_N$), a second input port (e.g., ports $\mathbf{242}_1$, $\mathbf{242}_2$, . . . $\mathbf{242}_N$) that is configured to receive a reference signal delivered through the line **225**, and an output port coupled to the analysis module **290** and electronic system **150**. Typically, each receiver channel **275** is coupled to a single receiver electrode. Each of the plurality of receiver channels **275** may include a charge accumulator **276** (e.g., charge accumulators $\mathbf{276}_1$, $\mathbf{276}_2$, . . . $\mathbf{276}_N$), supporting components **271** (e.g., components $\mathbf{271}_1$, $\mathbf{271}_2$, . . . $\mathbf{271}_N$) such as demodulator circuitry, a low pass filter, sample and hold circuitry, other useful electronic components filters and analog/digital converters (ADCs) or the like. The analog/digital converter (ADC) may comprise, for example, a standard 8, 12 or 16 bit ADC that is adapted to receive an analog signal and deliver a digital signal (receiver channel output signal) to the analysis module **290** (e.g. a Successive Approximation ADC, a Sigma-Delta ADC, an Algorithmic ADC, etc). In one configuration, the charge accumulator **276** includes an integrator type operational amplifier (e.g., Op Amps A_1-A_N) that has an integrating capacitance C_{fb} that is coupled between the inverting input and the output of the device. Due to the type of electronic elements required to detect and process the received resulting signals, the cost required to form the each receiver channel **275** is generally more expensive than the cost required to form the components in the signal generating processor **255** that provides the transmitter signal(s) to a transmitter electrode(s).

FIG. **3**A is a table that lists examples of various different sensing electrode connection configurations that can be used to form an array of transcapacitive sensing elements that are used to sense the positional information of an input object that is positioned over at least a portion of the array. Each row of the table contains a different sensing electrode configuration that can be advantageously used in one or more of the embodiments described herein. FIG. **3**B schematically illustrates the first sensing electrode configuration found in the table shown in FIG. **3**A (e.g., first row of the table), which has one transmitter electrode **312** (or transmitters Tx) and twelve receiving electrodes **311** (or receivers Rx) that are used to detect the positional information of an input object disposed over the array **310** of sensing elements. In this configuration, each of the receiving electrodes **311** can be separately poled by a sensor controller **218** (FIG. **2**A) by use of its dedicated trace **304** (e.g., 12 traces are shown in FIG. **3**B) when a transmitter signal is delivered through the transmitter electrode **312** via its dedicated trace **303**. Each of the receiving electrodes **311** and traces **304** and transmitter electrode **312** and trace **303** may be coupled to one or more components in the processing system **110**, such as the sensor controller **218**. The traces **303** and **304** are generally similar to the traces **212** and **213**, respectively, which were discussed above. In this way, each receiving electrode **311** and at least an adjacently positioned portion of transmitter electrode **312** form a sensing element **121** (FIGS. **1** and **2**A) that can be used to determine the positional information of an input object by knowing the position of each sensing element **121** in the array **310**. Therefore, to control the electrodes **311**, **312** in the array **310** it will require 13 total traces, which are illustrated as a group of traces **305**A. One skilled in the art will appreciate that FIG. **3**B can also be used to illustrate the sixth configuration disclosed in the table (e.g., 12 transmitters and 1 receiver) by swapping the function of the electrodes **311** and **312** from receiver electrodes to transmitter electrodes and transmitter electrode to receiver electrode, respectively. One will note that the capacitive coupling between electrodes is typically symmetric in most materials.

FIG. **3**C schematically illustrates the fourth sensing electrode configuration found in the table shown in FIG. **3**A, which has four transmitter electrodes **312** and three receiving electrode elements **311**A-**311**C that are all used to detect the positional information of an input object disposed over the array **310** of sensing elements illustrated in FIG. **3**C. In this configuration, each of the receiving electrode elements **311**A, **311**B and **311**C can be separately polled by a sensor controller **218** by use of its dedicated trace **304** (e.g., 3 traces are shown in FIG. **3**C) when a transmitter signal is delivered through one of the transmitter electrodes **312** via its dedicated trace **303**. Since the receiving electrode elements **311**A, **311**B and **311**C each comprise multiple interconnected sensor electrode elements, the sensing region **120** still contains the same number of sensing elements **121** as the configuration shown in FIG. **3**B. Each of the interconnected sensor electrode elements, or sometimes referred to herein as a sub-receiver electrode elements (e.g., four shown for each receiving electrode **311**A, **311**B and **311**C in FIG. **3**C), within its respective receiving electrode element **311**A, **311**B or **311**C will form a sensing element **121** with its adjacent transmitter electrode. In this example, the first sensor electrode element in the receiving electrode elements **311**A, which is adjacently positioned relative to the top transmitter electrode **312** in FIG. **3**C, forms one sensing element **121**, and the other receiving electrode elements **311**A that is adjacently positioned relative to the second transmitter electrode **312** from the top in FIG. **3**C will also form another sensing elements **121**, and so on for the other receiving electrodes and transmitting electrodes. One skilled in the art will appreciate that FIG. **3**C can also be used to illustrate the third configuration disclosed in the table (e.g., 3 transmitters and 4 receiver) by swapping the function of the electrodes **311** and **312** from receiver electrodes to transmitter electrodes and transmitter electrode to receiver electrode, respectively. However, to control the electrodes **311**, **312** in the array **310** shown in FIG. **3**C it will only require 7 total traces, which are contained in the group of traces **305**B. In the simple example illustrated in FIG. **3**C, the total number of traces can be can be reduced by about 46% from the configuration illustrated in FIG. **3**B.

The benefit of reducing the number of traces used in an input device is generally important in reducing the complexity and cost of the input device, since the sensing region **120** of most typical 3 inch up to 15 inch diagonal handheld devices today, such as a tablet, PDA or other similar device, require hundreds or even thousands of sensing elements **121** to reliably sense the position of one or more input objects, such as fingers. The reduction in the number of traces that need to be routed to the various processing system **110** components is desirable for a number of reasons, which include a reduction in the overall cost of forming the input device **100**, a reduction in the complexity of routing the multitude of traces **303** and **304** within the sensing region **120**, a reduced interconnecting trace length due to reduced routing complexity, a reduction in the cross-coupling of signals between adjacently positioned traces, and allowing for a tighter packing or increased density of electrodes **311** and **312** within the sensing region **120**. The reduction in the number of traces will also reduce the amount of cross-coupling between the traces due to a reduction in the

required trace density and number of traces that will transmit or receive signals delivered to or from adjacently positioned sensor electrodes or traces. Thus, one or more of the embodiments described herein, utilizes one or more of the techniques and electrode array configuration disclosed herein to reduce or minimize the number of traces and/or electrodes required to sense the position of an input object within the sensing region **120**. Reducing the number of electrodes may allow designs that significantly reduce cost and complexity to be created, even when a larger number of receiver electrodes are required.

Moreover, one skilled in the art will appreciate that input device **100** configurations that utilize a greater number of transmitter electrodes versus receiver electrodes may be desirable, due to a reduction in the system complexity and system cost created by the difference in the components required to generate the transmitter signals delivered by the transmitter electrodes versus the components required to receive and process the resulting signals received by each receiver channel from a receiver electrode. Referring to FIG. **2**B, the receiver channels **275** may include a charge accumulator **276** and supporting components **271**, such as demodulator circuitry, a low pass filter, sample and hold circuitry, other useful electronic components filters and analog/digital converters (ADCs), while the transmitter signals can be created and delivered by use of a signal generator **220** and one or more shift registers and/or simple electrical switches. Therefore, in some embodiments, the number of transmitter electrodes is greater than the number of receiver electrodes, such as the configurations 4-6 listed in the table found in FIG. **3**A. However, in some high speed or narrow bandwidth capacitive sensing applications it may be desirable to have a larger number of receiver electrodes versus transmitter electrodes, and thus some of the embodiments described herein can be used to reduce the total number of transmitter electrodes, required to reliably determine the positional information of an input object, relative to the number of required receiver electrodes.

While the discussion above and below generally describes an electrode (e.g., sensor electrodes **301**, **311**, **302**, **312**, etc.) as being a separate element from its dedicated trace (e.g., traces **303** and **304**), the separation of these elements is only made for clarity reasons, since each "sensor electrode" or "electrode" will generally include a trace and a sensor electrode element (e.g., body portion of a sensor electrode). In some configurations, a trace may also contain connecting elements that are used to interconnect multiple sensor electrode elements together to form a sensor electrode, such as the interconnecting trace elements **304**A that are each used to connect the receiving electrode elements **311**A together, as illustrated in FIG. **3**C. One skilled in the art will appreciate that each trace has a physical size that allows the delivered transmitter signals and/or received resulting signals to be transmitted from the sensor electrode element portion of the sensor electrode to the various processing system **110** components. Thus, each trace has a length and a cross-sectional area, which is defined by its thickness multiplied by its width, which both can be adjusted to assure that the resistance of this interconnecting component does not cause significant variation in the transmission or receipt of the capacitive sensing signals by the processing system **110** components. In some configurations the cross-sectional area of each trace is adjusted to compensate for the different lengths of the traces to assure that the resistance loss for each electrode is similar, no matter how close or far the electrode is from the various processing system components.

FIGS. **4**A-**17**B each illustrate the various configurations of sensing electrodes that can be used in conjunction with the processing system **110** components discussed above to determine the positional information of an input object that is disposed within the sensing region **120**. In general, the sensor electrode configurations illustrated in FIGS. **4**A-**4**K, **5**A-**5**C, **8** and **14** include a plurality of sensor electrodes that are configured to form a sensor electrode array (e.g., sensor electrode array **210**, **310**A-**310**K, **510**A-**510**K, etc.) that can be used as part of a larger sensor array set (e.g., sensor array set **200**, **600**, **650**, **700**, **900**A, **900**B, **1000**, etc.), which is used to sense the positional information of an input object that is disposed within the sensing region **120** of an input device **100**. While the sensor electrode configurations illustrated in FIGS. **4**A-**17**B contain many different numbers of sensor electrodes, these illustrations are not intended to limiting as to the scope of the invention described herein, since other numbers of each type of sensor electrode may be included without deviating from the basic scope of the invention described herein. The sensing electrodes can be disposed in an array of sensing electrodes, such as, for example, the sensing electrode arrays **310**A-**310**K in FIGS. **4**A-**4**K, sensing electrode arrays **510**A-**510**C in FIGS. **5**A-**5**C and sensing electrode array **810** in FIG. **8**, which in some cases may be positioned in larger sensor array sets that include arrays of sensing electrodes, such as the sensor array sets shown in FIGS. **4**J-**4**K, **6**A-**6**B, **7**, **9**A-**9**B, **10**, **11**A, **12**A-**12**B, **13**, **15**, **16**A and **17**A. Embodiments of the invention can be used to create a capacitive image using only sensor electrodes in a single layer disposed on a surface of a substrate. In some embodiments, no sensor electrodes are layered or jumpered within the sensing region **120**, which is used for capacitive sensing. The sensor electrodes described herein can, for example, be formed by patterning a blanket conductive layer comprising a thin metal layer (e.g., copper, aluminum, etc.) or a thin transparent conductive oxide layer (e.g., ATO, ITO, AZO) that is deposited on a surface of an optically clear substrate (e.g., glass), or in some cases optically opaque substrate, using convention deposition techniques known in the art (e.g., PVD, CVD, evaporation, sputtering, etc.).

FIGS. **4**A and **4**B each illustrate a portion of a sensor electrode pattern, or array of sensor electrodes **310**A and **310**B, respectively, that may be used to form a single layer capacitive imaging sensor. FIG. **4**A illustrates a plurality conductive routing traces, where sensor electrodes **301** and **302**A-**302**E are coupled to processing system **110** through one of the traces **303** and **304**. As is illustrated, a sensor electrode **301** may be patterned around a plurality of sensor electrodes **302**A-**302**E. In various embodiments, the traces **303** and/or **304** may all be routed to one side of sensor electrode pattern as illustrated in FIG. **4**B or to different sides as illustrated in FIG. **4**A, or in any other alternating or non-alternating pattern as desired. In some input device configurations, it is desirable to route the traces **303** and/or **304** to different sides of an array of sensor electrodes **310**A, as illustrated in FIG. **4**A, to assure that multiple arrays of sensor electrodes **310**A (see FIG. **6**A) can be closely spaced together and reduce the possibility that electric fields created by the signal transmission through the traces (e.g., traces **303**) will affect the measured resulting signal received by one or more of the electrodes found in an adjacently positioned array of sensor electrodes. In various embodiments the number of sensor electrodes may be adjusted to achieve a desired capacitive sensing resolution, pixel response and/or size of the sensor. The term "size" of an electrode or trace, as used herein, is generally intended to signify the difference in surface area of the electrode that is parallel to the surface that the electrode or

trace is positioned on, since the thickness of the material used to form the electrodes and/or traces is typically small compared to the electrode's or trace's dimensions parallel to the surface on which it is positioned, and will remain relatively constant across the entire sensing region **120**.

One skilled in the art will appreciate that the size of each type of electrode (i.e., transmitter or receiver) and the ratio (R) of the sizes of the electrodes (e.g., R=transmitter electrode surface area/receiver electrode surface area) will have an affect on the capacitive sensing characteristics of the processing system **110**. In many configurations, it is desirable to adjust the areas of the transmitter and receiver electrodes so that they are not equal, and thus the ratio of the areas is much greater than or much less than unity (e.g., R>>1 or R<<1). In some embodiments, sensor electrodes that are configured as transmitter electrodes (e.g., sensor electrode **802**A in FIG. **8**) are sized so that an adjacent edge(s) (e.g., right side vertical edge) are at least as long as the sum of the adjacent edges of the adjacently positioned receiver electrodes (e.g., left side vertical edges of the sensor electrode elements **801**A and **805**A in FIG. **8**).

In some embodiments, as illustrated in FIGS. **4**A-**7**, the sensor electrode **301** may be patterned so that it can capacitively couple with each sensor electrode, such as the sensor electrodes **302** (e.g., sensor electrodes **302**A-**302**E in FIG. **4**A). In various embodiments, sensor electrodes **301** and **302** and the traces **303**, **304** may comprise a similar material that is disposed over a surface of a substrate. In other embodiments, sensor electrodes **301** and **302** may comprise a first material and the traces **303**, **304** may comprise a second material, wherein the first and second materials are different. In various embodiments, the sensor electrodes and conductive routing traces may comprise substantially transparent materials or substantially optically invisible materials such as Indium Tin Oxide (ITO), thin metal wires or the like.

In some cases, the sensor electrode **301** may be configured to perform as a transmitter electrode and sensor electrodes **302** may be configured to perform as receiver electrodes. In other cases, the sensor electrode **301** may be configured to perform as a receiver electrode and sensor electrodes **302** may be configured to perform as transmitter electrodes. In various embodiments, the processing system **110** is configured to simultaneously receive resulting signals from sensor electrodes **302** while transmitting a transmitter signal from the sensor electrode **301**. In other embodiments, processing system **110** is configured to sequentially transmit transmitter signals through each of the sensor electrodes **302** while receiving resulting signals using the sensor electrode **301**.

In one embodiment, as illustrated in FIG. **4**A, sensor electrode **301** is patterned around each of the sensor electrodes **302**A-**302**E. In some embodiments, the sensor electrode **301** is patterned in such a way that it at least partially encloses each of the sensor electrodes **302**. The term "partially enclose," as used herein, is intended to describe a configuration where a portion of a first type of sensor electrode is disposed around a significant portion of the linear length of an edge or edges that define, or outline, the area of a second type of sensor electrode. In some embodiments, a first type of sensor electrode is said to partially enclose a second type of sensor electrode, where the first type of sensor electrode is disposed around the periphery of a second type of sensor electrode so that the centroid of the area of the second type of sensor electrode is at least disposed between opposing portions of the partially enclosing part of first type of electrode, while still allowing routing of the separate electrodes in a single layer. In one example, the sensor electrode **301** in FIG. **4**G is said to partially enclose the sensor electrode **302**A, since it is disposed around a significant portion of the sensor electrode **302**A, so that the centroid of the area (not shown) of the sensor electrode **302**A (triangular shaped electrode) is disposed between the top two segments of the sensor electrode **301**, which are adjacent to two of the three edges of the sensor electrode **302**A.

In one configuration, as shown in FIG. **4**A, the sensor electrode **301** is designed to meander around and between the sensor electrodes **302**A-**302**E, so that the conductive path that the electrode forms, between the connection side of the sensor electrode **301**, which is coupled to the trace **304**, and the furthest point away from the connection side (e.g., near sensor electrode **302**A), winds back and forth around a central axis (e.g., a vertical axis of symmetry in FIG. **4**A (not shown)) in which the array of sensor electrodes **310**A are aligned. In some cases, as shown in FIG. **4**A, the meander of the sensor electrode **301** may also wind around portions of each of the sensor electrodes **302**A-**302**E to at least partially enclose each electrode. While a portion of the sensor electrode **301** is illustrated as being disposed between each adjacent pair of sensor electrodes **302**A-**302**B, **302**B-**302**C, etc. in FIG. **4**A, this configuration is not intended to be limiting, since the meander of the sensor electrode **301** need not pass between each pair of adjacent sensor electrodes **302**A-**302**B, etc. and may only pass between one of the adjacently positioned pairs in the sensor electrode array **310**A. Moreover, in some configurations it may be desirable to maximize the length of the sensor electrode **301** to improve its sensitivity in receiving or transmitting a capacitive sensing signal between one or more of the adjacently positioned sensor electrodes **302**A-**302**E. The sensor electrode **301** may be similar in size to the trace **304** and comprise the same material as the material used to form each sensor electrode element **302**A-**302**E (e.g., layer of ITO), and thus may be formed during the patterning process used to form the sensor electrode elements.

In one embodiment, as illustrated in FIG. **4**A, the sensor electrode array **310**A includes a first type of sensor electrodes, such as sensor electrodes **302**A-**302**E that have a first sensor electrode shape (e.g., polygonal shape), that are at least partially enclosed by a second type of sensor electrode that has a second sensor electrode shape (e.g., wire shaped), which is different than the first sensor electrode shape. In one configuration, the sensor electrode array **310**A includes sensor electrodes **302**A-**302**E that have a polygonal shape, and are at least partially enclosed by a second type of sensor electrode **301** that has a shape that outlines the polygonal shape of the sensor electrodes **302**A-E. A shape of a sensor electrode that is spaced a repeatable or common distance from, or outlines, at least a portion of another sensor electrode is also defined herein as an electrode that has a complementary shape, or is a complementary shaped electrode. As shown in FIG. **4**A, the sensor electrode **301** may have a complementary shape, which is rectangular, that outlines the rectangular shaped sensor electrodes **302**A-E. Further, as shown in FIG. **4**A, the sensor electrode **301** may have a meandering shape that has a differing orientation for each of the one or more of the adjacently positioned sensor electrodes **302**A-**302**E. For example, the uppermost portion of the sensor electrode **301** has a C-shaped orientation that outlines the sensor electrode **302**A, and the adjacent portion of the sensor electrode **301** has an inverted C-shaped orientation (e.g., inverted horizontally) that outlines the sensor electrode **302**B.

In one embodiment, the sensor electrode **301** is patterned in such a way that it is disposed around pairs or larger groups of sensor electrodes, such as two or more sensor electrodes **302**A-**302**E. Therefore, the array of sensor electrode configurations illustrated herein are not intended to be limiting as to

the scope of the invention described herein, since the sensor electrode **301** can be disposed at least partially around two or more sensor electrodes without deviating from the basic scope of the invention described herein.

In another configuration, as illustrated in FIG. **4**B, the sensor electrode **301** is formed so that the conductive path that the sensor electrode forms, between the connection side of the sensor electrode **301**, which is coupled to the trace **304**, and the furthest position away from the connection side (e.g., near sensor electrode **302**A), is non-meandering and thus has a short path length (e.g., length of the portion of the electrode disposed on the left side of the sensor electrodes **302**A-**302**E in FIG. **4**B). As illustrated in FIG. **4**B, the sensor electrode **301** has a complementary shape, which is rectangular, that outlines the rectangular shaped sensor electrodes **302**A-E. Further, as shown in FIG. **4**B, the sensor electrode **301** may have a shape that has the same orientation for one or more of the adjacently positioned sensor electrodes **302**A-**302**E. For example, the uppermost portion of the sensor electrode **301** has a C-shaped orientation that outlines the sensor electrode **302**A, and an adjacent portion of the sensor electrode **301** also has a C-shaped orientation that outlines the sensor electrode **302**B. In some configurations it may be desirable to minimize the width of the sensor electrode **301** to reduce direct user input coupling to the electrode or increase the width to improve the RC time constant of the sensing device to allow for an increased capacitive sensing sampling rate (e.g., sensing frame rate).

FIG. **4**C illustrates an array of sensor electrodes **310**C that comprises a sensor electrode **301** that is patterned around the sensor electrodes **302**A-**302**E, which each have a distributed electrode shape, such as a zig-zag wire shape as shown. The zig-zag wire shape can also be formed in a sinusoidal, stepped or other waveform type shape, including irregular wave type shapes. In some cases, use of a distributed electrode shape, as shown in FIG. **4**C, may be preferred over a solid electrode shape, as shown in FIG. **4**A, to adjust the ratio of the transmitter and receiver electrode areas by adjusting the sensor electrode area formed in the distributed electrode shape to improve the capacitive sensing sensitivity of the input device. In various embodiments, the distributed electrode shape type of sensor electrodes may be formed in various different shapes, orientations, designs and sizes. In one example, sensor electrodes **302**A-**302**E, and their respective traces **303** may be comprised of the same materials and may have a similar cross-sectional size in its zig-zag wire shape. As illustrated in FIG. **4**C, the sensor electrode **301** has a complementary shape, which is rectangular, that outlines the rectangular peripheral shape of the sensor electrodes **302**A-E.

FIG. **4**D illustrates an array of sensor electrodes **310**D that comprises a segmented sensor electrode **301** that are each disposed around one or more of the sensor electrodes **302**A-**302**E. The array of sensor electrodes **310**D is similar to the array of sensor electrodes **310**A illustrated in FIG. **4**A, except that the sensor electrode **301** of FIG. **4**A has been segmented so that groups of one or more sensor electrodes **302**A-**302**E are at least partially enclosed in each of the formed segments **301**A-**301**C. In this way, the different segments **301**A-**301**C of the sensor electrode **301** can be separately polled at the same time or sequentially polled in time by the sensor controller components in the processing system **110**. In one embodiment, as illustrated in FIG. **4**D, the sensor electrode array **310**D includes a first type of sensor electrodes, such as sensor electrodes **302**A-**302**E that have a first electrode shape (e.g., polygonal shape), that are at least partially enclosed by a second type of sensor electrodes that have a second electrode shape (e.g., wire shaped).

FIG. **4**E illustrates an array of sensor electrodes **310**E that comprises an open circular or arc shaped sensor electrode **301** that is patterned around one or more of the circular sensor electrodes **302**A-**302**C. FIG. **4**F illustrates an array of sensor electrodes **310**F that comprises an open hexagonal shaped sensor electrode **301** that is patterned around one or more of the hexagonal shaped sensor electrodes **302**A-**302**B. As illustrated in FIGS. **4**E and **4**F, the sensor electrode **301** has a complementary shape, which is circular or hexagonal, that outlines the circular or hexagonal shaped sensor electrodes **302**A-E. The configurations of the traces **303** and **304** in FIGS. **4**E and **4**F are not intended to limiting, and thus can be oriented in any other desirable orientation. In some embodiments, a group of several arrays of sensor electrodes **310**E or **310**F (not shown), or sensor array set, may be positioned and oriented so that the adjacently positioned arrays of sensor electrodes **310**E or **310**F form a hexagonal close-packed pattern across the sensing region **120** to improve the density of the sensing electrode pattern.

FIG. **4**G illustrates an array of sensor electrodes **310**G that comprises a triangular shaped sensor electrode **301** that is disposed between and/or patterned around a portion of one or more of the triangular shaped sensor electrodes **302**A-**302**B. The array of sensor electrodes **310**G, shown in FIG. **4**G, includes a configuration in which the sensor electrode **301** is disposed adjacent to two edges of each of the sensor electrodes **302**A-**302**C. As noted above, the sensor electrode **301** in FIG. **4**G partially encloses the sensor electrode **302**A, since it is disposed around a significant portion of the sensor electrode **302**A. In one embodiment, the sensor electrode array **310**G includes sensor electrodes **302**A-**302**E, which have a triangular electrode shape, that are at least partially enclosed by a zig-zag or other similar shaped electrode that is disposed between the sensor electrodes **302**A-**302**E. As illustrated in FIG. **4**G, the sensor electrode **301** has a complementary shape that outlines at least a portion of the sensor electrodes **302**A-E.

FIG. **4**H illustrates an array of sensor electrodes **310**H that comprises a sensor electrode **301** that is patterned around one or more complex shaped sensor electrodes **302**A-**302**D. As illustrated in FIG. **4**H, the sensor electrode **301** has a complementary shape that outlines at least a portion of the sensor electrodes **302**A-D. FIG. **4**I illustrates an array of sensor electrodes **310**I that comprises a sensor electrode **301** that is disposed within one or more of the sensor electrodes **302**A-**302**D. Since the capacitive coupling between adjacently positioned sensor electrodes is generally governed by the length of the adjacent edges of each of the sensor electrodes in each sensing element **121**, it is often desirable to maximize the length of the adjacent edges of the sensor electrodes to maximize the capacitive coupling between the sensor electrodes. FIGS. **4**H and **4**I each generally illustrate sensor electrode configurations that interleave, or are interdigitated with each other in hopes of maximizing the length of the adjacent edges of the sensor electrodes to improve the capacitive coupling between the electrodes.

FIGS. **4**J and **4**K each illustrate a sensor array set **400**J, **400**K, respectively, that include sensor electrode arrays **310**J, **310**K, that each comprises a sensor electrode **301** that is disposed within one or more polygonal shaped sensor electrodes **302**A-**302**D. FIG. **4**K differs from FIG. **4**J in that the traces **303** and **304** in one of the array of sensor electrodes **310**K has been altered to change the symmetry of the electric fields and/or capacitive coupling generated across a portion of the sensing region **120**. In some configurations, one or more of the sensor electrode arrays can be formed in other orientations to alter the position or routing of the sensor electrodes

in adjacent sensor electrode arrays (e.g., mirror image of the sensor electrodes **301** and **302**A-D in adjacent sensor electrode arrays) to alter the electric fields formed by the sensor electrodes in the sensor electrode arrays within a sensor array set. Therefore, FIGS. **4**J and **4**K each illustrate another possible sensor electrode configuration that has sensor electrodes that interleave, or are interdigitated with, each other to maximize the length of the adjacent edges of the sensor electrodes to improve the capacitive coupling between the electrodes. This can optimize the ratio of user input signal relative to the direct coupling (e.g. of interference) of an input into either electrode. In one embodiment, as illustrated in FIGS. **4**I, **4**J and **4**K, the sensor electrode array **310**I-K includes a first type of sensor electrodes, such as sensor electrodes **302**A-**302**F that each have a first electrode shape (e.g., polygonal shape) that includes a plurality of recessed regions **391** in which a portion of a second type of sensor electrode (e.g., sensor electrode **301**) is disposed. In general, the gap formed between the edge of the first type of sensor electrodes and the second type of sensor electrodes in the recessed region **391** is small enough to assure ohmic isolation and sized to achieve a desirable capacitive coupling between the sensor electrodes. In one example, as shown in FIG. **4**J the sensor electrode **301** has a back-bone shape that includes a plurality of fingers **392**, which are arrayed in a pattern and are interconnect by one or more connecting segments **393**.

FIG. **5**A illustrates an alternative embodiment of a of sensor electrode array **510**A that includes a plurality of sensor electrodes **301** and **302**A-**302**E of a single layer capacitive sensor device that are positioned to form interdigitated sensor electrodes. In the illustrated embodiment, sensor electrode **301** is interdigitated with sensor electrodes **302**A-**302**E, such that one or more electrode segments **501** of each of the sensor electrodes **302**A-**302**E and electrode segments **502** of each of the one or more sensor electrode(s) **301** overlap in at least one direction (e.g., horizontal direction in FIG. **5**A). In one configuration, as illustrated in FIG. **5**A, the sensor electrode **301** has a meandering configuration that also includes the sensor electrode **301** that at least partially encloses each of the sensor electrodes **302**A-**302**E. The meandering configuration may also include a sensor electrode **301** that weaves between one or more the adjacent sensor electrodes **302**A-E, as well as at least partially enclosing one or more of the sensor electrodes **302**A-**302**E This sensor electrode configuration will tend to maximize the length of the adjacent edges of the sensor electrodes **301** and **302** to improve the capacitive coupling between each pair of sensor electrodes in each sensing element **121** (e.g., sensor electrode **302**A and a portion of sensor electrode **301**).

In other embodiments, the sensor electrodes **301** and **302** may be interdigitated or interleaved in various other orientations. FIG. **5**B illustrates an array of sensor electrodes **510**B. In one example, while the embodiment illustrated in FIG. **5**A illustrates a horizontal orientation of the interdigitated electrode segments **501** and **502**, in other embodiments a vertical orientation, such as the interdigitated electrode segments **506** and **505** of the sensor electrodes **301** and **302**, respectively, may be used. Therefore in one embodiment, sensor electrode **301** is interdigitated with sensor electrodes **302**A-**302**E, such that one or more electrode segments **505** of each of the sensor electrodes **302**A-**302**E and electrode segments **506** of each of the one or more sensor electrode(s) **301** overlap in one direction (e.g., vertical direction in FIG. **5**B). One skilled in the art will appreciate that other orientations of the interdigitated electrodes may be used.

FIG. **5**C illustrates another embodiment of an interdigitated single layer sensor electrode pattern, or array of sensor electrodes **510**C. In this illustrated embodiment, a sensor electrode **301** is interdigitated with sensor electrodes **302**A-**302**H. As compared to the embodiment of FIG. **5**A, in the embodiment illustrated in FIG. **5**C, two different sensor electrodes **302** are interdigitated with a portion of sensor electrode **301**, whereas a single sensor electrode **302** is interdigitated with that same portion of sensor electrode **301** in the embodiment illustrated in FIG. **5**A. In other embodiments, more than two sensor electrodes **302** may be interdigitated with each portion of sensor electrode **301**.

FIG. **6**A schematically illustrates a sensor array set **600**, which may comprise two or more sensor electrode arrays **610**. In one example, as shown in FIG. **6**A, the four sensor electrodes arrays **610** are disposed within a sensing region **120** to determine the positional information of an input object by use of a capacitive sensing technique. The sensor electrode arrays **610** may be similar to the sensor electrode array **310**A illustrated in FIG. **4**A, as shown, or in any other similar sensor array configuration as shown in FIGS. **4**B-**4**K and **5**A-**5**B or variants thereof. In various embodiments, each of the traces **303** and **304** may be coupled to the sensor controller **218** (FIG. **2**A) so that the sensors in the sensor array set can be driven for capacitive sensing. The traces **303** and **304** may form part of or replace the traces **212** and **213**, respectively, discussed above in conjunction with FIGS. **2**A-**2**B.

In one example, the sensor electrodes **302**A-**302**E in the sensor electrode arrays **610** may be used as transmitter electrodes and the sensor electrodes **301** may be used as receiver electrodes. The input device containing the sensor electrode arrays **610** may be operated such that one transmitter electrode transmits at one time, or multiple similarly positioned transmitter electrodes transmit at the same time. In this example, multiple sensor electrodes **302**A-**302**E in each sensor electrode array **610** transmit different transmitter signals according to one or more coding schemes that enable their combined effects on the resulting signals received by the receiving type sensor electrodes **301**, to be independently determined. The receiver type sensor electrodes **301**, may be operated singly or multiply to acquire resulting signals created from the transmitter signal to determine measurements of the capacitive couplings at the capacitive pixels, which are used to determine whether an input object is present and its positional information, as discussed above. The resulting signals may be received at one instant in time, or by scanning the each of the various sensing elements distributed across the sensing region **120** or other useful scanning technique.

FIG. **6**B schematically illustrates a sensor array set **650**, which comprises two or more sensor electrode arrays **610**. The sensor array set **650** is similar to the sensor array set **600** shown in FIG. **6**A, but includes a configuration that contains a shield electrode **670** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **661** and **662**. To improve the manufacturability of the input device, reduce its manufacturing cost and improve its device yield it is desirable to eliminate the use of jumpers within the sensing region and route all of the traces so that the connections made to the external components can be made outside of the sensing region **120** and near the edge of the substrate on which the electrodes are formed.

As illustrated in FIG. **6**B, the routing of the traces **303** and **304** exit two sides of the sensing region **120**. While its generally desirable to have the traces be routed out a single side of the sensing region **120** for ease of forming connections with other external components and reducing the required overall size of the substrate (e.g., substrate **209** in FIG. **2**A) on which the sensor electrodes are disposed, a two or more sided

trace routing scheme may be needed as the density or pattern of the sensor electrodes in the sensor electrode arrays **610** or sensor array set **650** becomes more complex. While routing of the traces out of more than one side of the sensing region **120** is only illustrated in FIG. **6**B, one skilled in the art will appreciate that any of the other configurations of sensor array sets or variations thereof may benefit from this type of trace routing configuration.

In the embodiment illustrated of FIG. **6**B, the shield electrode **670** (or guard electrode) is disposed over portions of the surface on which the sensor electrodes **301** and **302**A-**302**J are formed. The shield electrode **670**, which are similarly labeled in the figures discussed below as reference numerals **770**, **970**, **1070**, **1270**, **1570** and **1670**, is generally used to shield the sensor electrodes and associated conductive traces **303** and **304** from each other to prevent or minimize the cross-talk between adjacently positioned and closely spaced traces and/or sensor electrodes. The shield electrode **670** may be coupled to a substantially constant voltage such as system ground, or any other substantially constant voltage, or varying voltage, which is able to shield nearby sensor electrodes and traces from each other. In general, the shield electrode **670** is useful to help improve the coupling of the input object **140** (FIG. **1**) to the input device's ground, and thus reduce the often large variability seen in the capacitive sensing measurements collected when the chassis of the input device **100**, such as a cell phone, is not in sufficient electrical contact with the input object, such as the finger of the input device user. The shield electrode **670** may comprise one or multiple electrodes either coupled to one another or driven with a similar signal (e.g., system ground). In FIG. **6**B, and other figures discussed herein, one or more portions of the shield electrode **670** may be coupled together in the external regions **661** and **662**, and connected to an input device **100** system ground and/or chassis of the input device **100** by a trace **605**. In various embodiments, the material from which the shield electrode is formed is the same as the material from which the sensor electrodes are formed, and thus in some embodiments, can be formed out of the same blanket layer of material during the sensor electrode patterning process. In various embodiments, the sensor electrodes, shield electrode(s) and conductive routing traces may comprise substantially transparent materials or substantially optically invisible materials such as Indium Tin Oxide (ITO), thin metal wires, metal layer or the like.

FIG. **7** schematically illustrates a sensor array set **700**, which comprises two or more sensor electrode arrays **710**. In one example, as shown in FIG. **7**, the four sensor electrodes arrays **710** are disposed within a sensing region **120** to determine the positional information of an input object by use of the various processing system **110** components that are discussed above. The sensor array set **700** is similar to the sensor array set **650** shown in FIG. **6**B, but includes a sensor array similar to the configurations shown in FIG. **5**A. The sensor array set **700** also includes a shield electrode **770** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **762**. In FIG. **7**, the one or more components of the shield electrode **770** may be coupled together in the external regions **762**, and also connected to a system ground and/or chassis of the input device **100** by a trace **705**. In one example it is also possible to connect neighboring groups of electrodes **303** to different interconnection traces in the external region so that electrodes (e.g. transmitters) associated with neighboring receivers transmit at different times or polarities to reduce or detect total input coupling from the user input to those neighboring groups of electrodes.

FIGS. **8**-**17**B illustrate various different configurations of sensor electrodes that generally comprise a plurality of sensor electrodes that are arranged in groups of adjacently positioned sensor electrodes that are combined to form an array of sensor electrodes that can be used to form a sensor electrode set. Each group of adjacently positioned sensor electrodes may contain two or more sensor electrodes that are used to form one or more sensing elements **121**. In some embodiments, one or more of the sensor electrodes in a sensor electrode array may be used as a transmitter electrode and one or more of the other sensor electrodes may be used as a receiver electrode. In one example, the sensor electrodes **802**A-**802**D in one or more of the sensor electrode arrays (e.g., sensor electrode arrays **810**, **910**A-D, **1010**A-D, **1010**A-D, **1110**A-B, **1210**A-D, **1310**A-D, **1510**A-D, **1610**A-D and **1710**A-D) may be used as transmitter electrodes and the sensor electrodes **801** and **805** may be used as receiver electrodes. The input device containing the sensor electrode arrays may be operated such that one transmitter electrode transmits at one time, or multiple similarly positioned transmitter electrodes transmit at the same time. In this example, multiple sensor electrodes **802**A-**802**D in each sensor electrode array transmit the same or different transmitter signals. The receiver type sensor electrodes **801** and **805**, may each be operated singly or multiply to acquire the resulting signals to determine measurements of the capacitive couplings at the capacitive pixels (e.g., sensing elements **121**) to determine the positional information of an input object. The resulting signals may be received at one instant in time, or by scanning the rows and/or columns of sensing elements distributed across the sensing region **120** in a raster scanning pattern (e.g., serially polling each sensing element separately in a desired scanning pattern), row-by-row scanning pattern, column-by-column scanning pattern or other useful scanning technique.

FIG. **8** illustrates a sensor electrode array **810** that comprises a plurality of sensor electrodes that are arranged in groups of three adjacently positioned sensor electrodes, such as sensor electrodes **801**, **805** and one of the sensor electrodes **802**. In this configuration, each group of sensor electrodes is used to form two sensing elements **121**, as shown at the top of FIG. **8**. In the illustrated embodiment, sensor electrodes **802**A-**802**D are individually coupled to a different trace **803**, while sensor electrodes **801** and **805** comprise multiple sensor electrode elements **801**A, **805**A that are each coupled together through a common trace **804**A and **804**B, respectively. As illustrated in FIG. **8**, a sensor electrode element **801**A, **805**A from each sensor electrode is disposed adjacent a different sensor electrode **802** (e.g., sensor electrodes **802**A-**802**D) within the group. In other embodiments, each sensor electrode element **801**A, **805**A may be separately coupled to its own separate trace. In such embodiments, each of the sensor electrode elements may be configured to operate as individual sensor electrodes or as elements of larger sensor electrodes. Further, while the sensor electrode elements **801**A, **805**A are illustrated as being part of either the sensor electrode **801** or sensor electrode **805**, in other embodiments the sensor electrode elements may be configured to form any number of sensor electrodes.

As described above, in relation to FIG. **2**A, sensor electrodes **802**A-**802**D may be configured to transmit transmitter signals and while sensor electrodes **801** and **805** (and related sensor electrode elements) may be configured receive the resulting signals formed from the transmitter signals. Alternately, sensor electrodes **801** and/or **805** may be configured to transmit transmitter signals, while sensor electrodes **802**A-**802**D may be configured to receive the formed resulting signals.

As illustrated in FIG. **8**, the sensor electrode elements **801**A and **805**A can each be coupled together, such that the top sensor electrode element in a portion of each group of sensor electrode elements are coupled together to form the sensor electrode **801** and the bottom sensor electrode element in the portion of the group of sensor electrode elements are coupled together to form the sensor electrode **805**. In other embodiments, the sensor electrode elements may be coupled together in other desirable ways. For example, the bottom sensor electrode element adjacent to sensor electrode **802**A may be coupled to the top sensor electrode element adjacent to sensor electrode **802**B, and the bottom sensor electrode element adjacent to sensor electrode **802**B may be coupled to the top sensor electrode element adjacent to sensor electrode **802**C, Such a coupling pattern may continue throughout the sensor electrode pattern or it may be varied through the sensor electrode pattern.

In various embodiments, the number of traces may be reduced by nearly half, as compared with configurations that have one sensor electrode element for each trace. Further, the sensor electrode pattern illustrated in FIGS. **8**-**17**B, may provide an improved signal to noise ratio and/or provide a capacitive pixel response that is wider which provides increased response to smaller input objects (e.g., smaller than 5 mm) over other more conventional designs. In other embodiments, the sensor electrode pattern of FIG. **8** may provide a connection between the sensor and processing system **110** with a reduced number of interconnecting vias in the flex (a reduction of about fifty percent) (i.e., reference numeral **251** in FIG. **2**A). Further, the sensor electrode pattern of FIG. **8** may provide for an increased capacitive frame rate. As noted above, by use of one or more of the sensor electrode interconnecting schemes disclosed herein, the number of traces and/or electrodes required to sense the position of an input object within the sensing region can be reduced without affecting the accuracy and repeatability of the acquired positional data.

FIG. **9**A schematically illustrates a sensor array set **900**A, which comprises two or more sensor electrode arrays **910**, such as sensor electrode arrays **910**A-**910**D. FIG. **9**B schematically illustrates another sensor array set configuration, or sensor array set **900**B, which comprises two or more sensor electrode arrays **910**. Each of the sensor electrode arrays **910**A-**910**D in the sensor array sets **900**A and **900**B contain the sensor electrode array **810** shown in FIG. **8**. The sensor electrode arrays **910**A-**910**D in the sensor array set **900**A are oriented so that the sensor electrodes **801** and **805** in adjacent sensor electrode arrays (e.g., sensor electrode arrays **910**A and **910**B) are positioned adjacent to each other, while the sensor electrode arrays **910**A-**910**D in the sensor array set **900**B are each oriented in the same direction. In some applications it may be desirable to orient sensor electrodes arrays so that the sensor electrodes of the same type, such as sensor electrodes **802** or sensor electrodes **801** and **805** are near to each other, such as shown in FIG. **9**A, to reduce the cross-talk between sensor electrodes and their respective traces of the opposite type, such as illustrated in FIG. **9**B.

The sensor array sets **900**A and **900**B may also include a shield electrode **970** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **962**. The portions of the shield electrode **970** that are disposed between the sensor electrodes and their associated traces can help reduce the cross-talk between sensor electrodes, which may be especially useful for configurations that have sensor electrodes of opposing types adjacent to each other, such as shown in FIG. **9**B. The one or more components of the shield electrode **970** may be coupled together in the external regions **962**, and also connected to a system ground and/or chassis of the input device **100** by a trace **905**.

FIG. **10** schematically illustrates a sensor array set **1000**, which comprises two or more sensor electrode arrays **1010**, such as sensor electrode arrays **1010**A-**1010**D. Each of the sensor electrode arrays **1010**A-**1010**D in the sensor array set **1000** are generally different from the sensor electrode array **810** shown in FIG. **8**, since the sensor electrode elements **801**A and **805**A in each sensor electrode array are positioned so that the bottom sensor electrode element **805**A, which is adjacent to a first sensor electrode (e.g., electrode **802**A), is coupled to the top sensor electrode element **805**A that is adjacent to a second sensor electrode (e.g., electrode **802**B), and the bottom sensor electrode element **801**A, which is adjacent to the second sensor electrode, may be coupled to the top sensor electrode element **801**A that is adjacent to a third sensor electrode (e.g., electrode **802**C), and so on, as is shown in FIG. **10**. Such a coupling pattern of the sensor electrode elements may continue throughout the sensor electrode array or it may be varied through the sensor electrode pattern.

Therefore, in one example, a capacitive image sensor may comprise a first set of sensor electrodes comprising a first sensor electrode element **801**A, a second sensor electrode element **805**A and a third sensor electrode element **801**A, and the first sensor electrode element **801**A is electrically coupled to the third sensor electrode element **801**A, and a second set of sensor electrodes comprising a fourth sensor electrode **802**A and a fifth sensor electrode **802**B, wherein the fourth sensor electrode **802**A is configured to capacitively couple with the first sensor electrode element **801**A, and the fifth sensor electrode **802**B is configured to capacitively couple with the third sensor electrode element **801**A. In the configuration illustrated in FIG. **10**, the third sensor electrode element **801**A is disposed between the first sensor electrode and the second sensor electrode. Whereas, in the configuration illustrated in FIG. **8**, the second sensor electrode element **805**A may be disposed between the first sensor electrode element **801**A and the third sensor electrode element **801**A.

The sensor array set **1000** may also include a shield electrode **1070** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **1062**. The one or more components of the shield electrode **1070** may be coupled together in the external regions **1062**, and also connected to a system ground and/or chassis of the input device **100** by a trace **1005**.

FIG. **11**A schematically illustrates a sensor array set **1100**, which comprises two or more sensor electrode arrays, such as sensor electrode arrays **1110**A-**1110**B. FIG. **11**B is a close-up view of a few sensor electrodes that are positioned within the sensor electrode array **1110**B, in the sensor array set **1100**. In various embodiments, one or more of the sensor electrodes elements in a sensor electrode includes a grounded region **1130** (FIG. **11**B) that is disposed within at least a portion of the sensor electrode element and is coupled to a ground trace **1120**. The ground traces **1120** may be coupled together in an external region that is outside of the sensing region **120**, and also be connected to a system ground and/or chassis of the input device **100**. The grounded region **1130** may comprise a conductive layer that is ohmically isolated from the sensor electrodes **1101**, **1102** or **1105**. In one example, the grounded region **1130** is formed from a portion of the conductive layer that is patterned to form each of the sensor electrodes. In some configurations, one or more of the sensor electrode elements **1101**A, **1102**A-E, **1105**A in one or more of the sensor elec-

trodes **1101**, **1102** or **1105** at least partially enclose a region that has a conductive layer disposed therein, and the conductive layer is coupled to a system ground and/or chassis of the input device **100**. In one example, the grounded region **1130** is disposed within the center of a sensor electrode element, since this is a region of the sensor electrode element that provides or receives the smallest amount of capacitive sensing signal and thus will not dramatically alter the capacitive sensing measurement.

The addition of the grounded region **1130** within the sensor electrode element will reduce the size, or effective surface area, of the sensor electrode element. In general, the addition of the grounded region **1130** within one or more of the sensor electrode elements can be used to adjust the ratio of the electrode areas (e.g., low ground mass effect) between adjacent opposing electrodes, which is important for controlling the signal quality and reducing the variability in the signals received by the receiving electrodes. The addition of the grounded region **1130** within one or more of the sensor electrode elements is also useful to increase the size of the ground plane in the input device to improve the coupling of the input object to the ground plane to reduce the variability in the measure capacitive sensing signal created by variations in the coupling of the input object to the system ground. The addition of the grounded region **1130** within one or more of the sensor electrode elements will also reduce the amount of cross-talk between sensor electrodes in one or more sensor arrays by shunting the unwanted signals, and also reduce the unwanted effects of EMI.

Further, in one embodiment of the input device **100**, each of the sensor electrode arrays **1110**A-B comprise a plurality of sensor electrodes that are arranged so that each sensor electrode (e.g., sensor electrode **1102**A-E) is associated with at least a portion of a sensor electrode element **1101**A and **1105**A of the sensor electrodes **1101**, **1105**. In this configuration, each group of sensor electrodes is used to form two sensing elements **121** (not shown), which is similar to the configuration shown at the top of FIG. **8**. In the illustrated embodiment, sensor electrodes **1102**A-**1102**E are individually coupled to a different trace **1103**, while sensor electrodes **1101** and **1105** comprise multiple sensor electrode elements **1101**A, **1105**A that are each coupled together through a common trace **1104**A and **1104**B, respectively. As illustrated, a sensor electrode element **1101**A, **1105**A from each sensor electrode is disposed adjacent a different sensor electrode **1102** (e.g., sensor electrodes **1102**A-**1102**E) within the group.

In other embodiments, each sensor electrode element **1101**A, **1105**A may be separately coupled to its own separate trace. In such embodiments, each of the sensor electrode elements may be configured to operate as individual sensor electrodes or as elements of larger sensor electrodes. Further, while the sensor electrode elements **1101**A, **1105**A are illustrated as being part of either the sensor electrode **1101** or sensor electrode **1105**, in other embodiments the sensor electrode elements may be configured to form any number of sensor electrodes. As described above, in relation to FIG. **2**A, sensor electrodes **1102**A-**1102**E may be configured to transmit transmitter signals and while sensor electrodes **1101** and **1105** (and related sensor electrode elements) may be configured receive the resulting signals formed from the transmitter signals. Further, sensor electrodes **1101** and/or **1105** may be configured to transmit transmitter signals, while sensor electrodes **1102**A-**1102**E may be configured to receive the formed resulting signals. In a further embodiment, the electrode region **1130** may be driven with a transmitter signal in a separate mode to be received by other electrodes (e.g. **1102**, **1101**, **1104**) or the electrode may be electrically floated (e.g. ohmically disconnected) to affect the sensing in some modes, while it is grounded in others.

FIG. **12**A schematically illustrates a sensor array set **1200**A, which comprises two or more sensor electrode arrays **1210**, such as sensor electrode arrays **1210**A-**1210**D. FIG. **12**B schematically illustrates another sensor array set configuration, or sensor array set **1200**B, which comprises two or more sensor electrode arrays **1210**. Each of the sensor electrode arrays **1210**A-**1210**D in FIGS. **12**A-**12**B comprise sensor electrodes **801**, **802** and **805** that are arranged in a staggered or an alternating sensor electrode layout. As is illustrated, each of the sensor electrode arrays contain alternating rows that are flipped or formed in a mirror representation of the sensor electrode group found in an adjacent row that is above and below. It is believed that the staggered or an alternating sensor electrode layout may provide an improved capacitive sensing sensitivity, due to the alternating electric field formation direction between each adjacent group of sensor electrode elements. In one example, where sensor electrodes **802**A is a transmitter electrode and the top sensor electrode elements **801**A and **805**A are receiving electrodes in sensor electrode array **1210**A the electric field will be created from left to right, while the adjacent group comprising sensor electrodes **802**B, which is a transmitter electrode, and the second sensor electrode elements **801**A and **805**A from the top, which are the receiving electrodes, will create an electric field from right to left. In general, each of the sensor electrode elements (e.g., elements **801**A, **802**A-**802**D, **805**A) in each sensor electrode array are staggered across a center-line **1221** that is disposed between the sensor electrode elements, as illustrated in sensor electrode array **1210**A of FIG. **12**A. It should be noted that, in general, the center-line of each staggered sensor electrode **801**, **802**, and **805** need not be collinear with the other staggered sensor electrodes.

The sensor electrode arrays **1210**A-**1210**D in the sensor array set **1200**A are oriented so that the sensor electrodes **801** and **805** in adjacent sensor electrode arrays (e.g., sensor electrode arrays **1210**A and **1210**B) are oriented in the same direction, while the sensor electrode arrays **1210**A-**1210**D in the sensor array set **1200**B are each oriented so that the same sensor electrode elements in adjacent sensor electrodes arrays are positioned adjacent to each other. In some applications it may be desirable to orient sensor electrodes arrays so that the sensor electrodes of the same type, such as sensor electrodes **802** or sensor electrodes **801** and **805** are near to each other, such as shown in FIG. **12**B, to reduce the cross-talk between sensor electrodes and their respective traces of the opposite type, such as illustrated in FIG. **12**A. In various other embodiments, the sensor electrode pattern in each sensor electrode array may be varied in other ways. For example, instead on a row by row basis, the sensor electrode pattern in each sensor electrode array may be varied every two rows or more. Further, while each column of the sensor electrode pattern is illustrated in FIG. **12**A as being similar, in other embodiments, the columns may differ. For example at least one of the columns may be a mirror image of the others, such that one or more of the columns may be flipped along its vertical axis.

The sensor array sets **1200**A and **1200**B may also include a shield electrode **1270** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **1262**. The one or more components of the shield electrode **1270** may be coupled together in the external regions **1262**, and also connected to a system ground and/or chassis of the input device **100** by a trace **1205**.

As described in relation to the embodiment illustrated in FIG. **8**, the sensor electrode elements of FIGS. **12**A-**12**B are coupled together such that the top sensor electrode element of each sensor electrode element pair is coupled together and the bottom sensor electrode element of each sensor electrode element pair is coupled together. In other embodiments, the sensor electrode elements may be coupled together in other ways. For example, the bottom sensor electrode element adjacent to a first sensor electrode may be coupled to the top sensor electrode element adjacent to a second sensor electrode, and the bottom sensor electrode element adjacent to the second sensor electrode may be coupled to the top sensor electrode element adjacent to a third sensor electrode, which is similar to the non-staggered configuration illustrated in FIG. **10**. Such a coupling pattern may continue throughout the sensor electrode arrays within these staggered or alternating sensor electrode layouts.

FIG. **13** illustrates a sensor array set **1300** that includes arrays of sensor electrodes **1310**A-**1310**D that each comprise a plurality of sensor electrodes that are arranged in groups of four adjacently positioned sensor electrodes elements, such as sensor electrode elements **1301**A, **1302**A, **1303**A found in the sensor electrodes **1301**, **1302**, **1303** and one of the sensor electrodes **802**. In this configuration, each group of sensor electrodes is used to form three sensing elements **121** (not shown in FIG. **13**), which, for example may each include sensor elements **802**A and **1301**A, sensor elements **802**A and **1302**A and sensor electrode elements **802**A and **1303**A. In the illustrated embodiment, each of the sensor electrodes **802**A-**802**D in each sensor electrode array are individually coupled to a different trace **803**, while sensor electrodes **1301**, **1302** and **1303** comprise multiple sensor electrode elements **1301**A, **1302**A, **1303**A that are each coupled together through a common trace **1304**A, **1304**B and **1304**C, respectively. As illustrated, a sensor electrode element **1301**A, **1302**A, **1303**A from each sensor electrode is disposed adjacent a different sensor electrode **802** (e.g., sensor electrodes **802**A-**802**D) within the group. In other embodiments, each sensor electrode element **1301**A, **1302**A, **1303**A may be separately coupled to its own separate trace. In such embodiments, each of the sensor electrode elements may be configured to operate as individual sensor electrodes or as elements of larger sensor electrodes. As described above, in relation to FIG. **2**A, sensor electrodes **802**A-**802**D may be configured to transmit transmitter signals and while sensor electrodes **1301**, **1302** and **1303** (and related sensor electrode elements) may be configured receive the resulting signals formed from the transmitter signals. Alternately, sensor electrodes **1301**, **1302**, **1303** may be configured to transmit transmitter signals, while sensor electrodes **802**A-**802**D may be configured to receive the formed resulting signals.

In other variations of the sensor electrode configuration shown in FIG. **13**, the sensor electrode elements may be coupled together in other desirable ways. For example, the bottom sensor electrode element adjacent to sensor electrode **802**A may be coupled to the top sensor electrode element adjacent to sensor electrode **802**B, and the bottom sensor electrode element adjacent to sensor electrode **802**B may be coupled to the top sensor electrode element adjacent to sensor electrode **802**C, such a coupling pattern may continue throughout the sensor electrode pattern or it may be varied through the sensor electrode pattern. Further, while each column of the sensor electrode pattern is illustrated in FIG. **13** as being similar, in other embodiments, the sensor electrode configuration in two or more columns may differ. For example at least one pair of adjacent sensor electrode arrays may be a mirror image of the others, such that one or more of the columns may be flipped along its vertical axis relative to the other sensor electrode array.

The sensor array set **1300** may also include a shield electrode **1370** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **1362**. The one or more components of the shield electrode **1370** may be coupled together in the external regions **1362**, and also connected to a system ground and/or chassis of the input device **100** by a trace **1305**.

In one embodiment, as illustrated in FIG. **14**, a sensor electrode array **1400** may comprise features that provide a more uniform signal response between the sensor electrodes in the sensor electrode array. FIG. **14** illustrates a sensor electrode set **1400** that includes an array of sensor electrodes that comprises a plurality of sensor electrodes that are each arranged in groups of three adjacently positioned sensor electrodes elements, such as sensor electrode elements **1401**A and **1405**A found in the sensor electrodes **1401**, **1405**, respectively, and one of the sensor electrodes **802** (e.g., sensor electrodes **802**A-**802**D). In this configuration, each group of sensor electrodes is used to form two sensing elements **121** (not shown in FIG. **14**), as similarly discussed above. In the illustrated embodiment, each of the sensor electrodes **802**A-**802**D in the sensor electrode array is individually coupled to a different trace **803**, while sensor electrodes **1401** and **1405** comprise multiple sensor electrode elements **1401**A, **1405**A that are each coupled together through a common trace **1404**A and **1404**B, respectively. As described above, in relation to FIG. **2**A, sensor electrodes **802**A-**802**D may be configured to transmit transmitter signals and while sensor electrodes **1401**, **1405** (and related sensor electrode elements) may be configured receive the resulting signals formed from the transmitter signals, or vice versa.

In one embodiment, each of the sensor electrode elements **1405**A each include conductive protrusions **1406** that are attached to and extend from the body portion **1405**B of the sensor electrode element **1405**A. In this configuration, the conductive protrusions **1406** may be oriented and positioned so that they even out the difference in the resulting signal received by the sensor electrode **1405** versus the sensor electrode **1401**, due to the positioning of an unconnected trace **1404**A or other similar element that is disposed between the sensor electrode elements **1405**A and the sensor electrodes **802**A-**802**D. Therefore, in some configurations, one or more of the conductive protrusion **1406** may extend in one or more directions from the body portion **1405**B of the sensor electrode element **1405**A to a position near the sensor electrode element **1401**A, such as between the adjacently positioned sensor electrode element **1401**A and a portion of its trace **1404**A. In one configuration, the conductive protrusions **1406** are positioned substantially parallel to the trace **1404**A and/or extend from one or more regions of the body portion **1405**B of the sensor electrode element **1405**A. The conductive protrusions **1406** may be similar in size to the trace **1404**A and comprise the same material as the material used to form each sensor electrode element **1405**A (e.g., layer of ITO), and thus may be formed during the patterning process used to form the sensor electrode elements. The conductive protrusions **1406** may alternately comprise a bonded wire or other similar conductive material.

FIG. **15** illustrates an alternate embodiment of a single layer sensor array set **1500** that includes multiple sensor electrode arrays **1510**A-**1510**D that comprise sensor electrodes that have a distributed electrode shape, such as the sensor electrodes illustrated and discussed in conjunction with FIG. **4**C above. In this configuration, each group of

sensor electrodes is used to form two sensing elements **121** (not shown in FIG. **13**), which, for example, may include sensor elements **802**A and **801**A and sensor elements **802**A and **805**A. In the illustrated embodiment, each of the sensor electrodes **802**A-**802**D in each sensor electrode array are individually coupled to a different trace **1503**, while sensor electrodes **801** and **805** comprise multiple sensor electrode elements **801**A, **805**A that are each coupled together through a common trace **1504**A and **1504**B, respectively. In various embodiments, the sensor electrodes **801**, **802**A-**802**D and **805**, which are illustrated in FIG. **15**, may comprise the same materials as the traces **1503**, **1504**A and **1504**B and/or may have a similar cross-sectional size in its zig-zag wire shape. In various embodiments, the sensor electrodes may be disposed in various other shapes and designs, versus a zig-zag type pattern as shown. The sensor electrode structure illustrated in the embodiment of FIG. **15** may be combined with any other embodiment described here within.

The sensor array set **1500** may also include a shield electrode **1570** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **1562**. Portions of the shield electrode **1570** can be coupled together in the external region **1562** and attached to ground trace **1505** that may coupled to an external ground or a chassis of the input device **100**.

FIG. **16**A illustrates an alternate embodiment of a single layer sensor array set **1600** that includes multiple sensor electrode arrays **1610**A-**1610**D that comprise sensor electrodes that have a distributed electrode shape similar to the configuration illustrate in FIGS. **4**C and **15** above. FIG. **16**B is a close-up view of a group of sensor electrodes found in one of the sensor electrode arrays **1610**A-**1610**D in the sensor array set **1600**. In this illustrated configuration, each group of sensor electrodes is used to form two sensing elements **121** (FIG. **16**B), which, for example, may include sensor elements **802**A and **801**A and sensor elements **802**A and **805**A. The sensor electrode elements **801**A and **805**A are found within the sensor electrodes **801** and **805**, which are each coupled together through a common trace **1604**A and **1604**B, respectively. Each of the sensor electrodes **802**A-**802**D in each sensor electrode array are individually coupled to a different trace **1603** and include a distributed electrode shape that may have two or more electrode regions **1630** and **1631** (FIG. **16**B) that have a different electrode shape or pattern to compensate for some physical or electrical attribute of the sensor electrodes in a sensor electrode group.

In one embodiment, as shown, the area density of the electrode material in a first electrode region **1630** of a sensor electrode **802** is different than the area density of the electrode material in a second electrode region **1631** of the same sensor electrode **802**. In this configuration, the area density of the of the sensor electrode **802** has been adjusted in the first electrode region **1631** versus the second electrode region **1632** to compensate for the additional electrode surface area provided by the connection element **1608** of the trace **1604**A that is coupled to the sensor electrode element **801**A versus the similarly positioned sensor electrode element **805**A. In this way, the higher density second electrode region **1631** will have an improved capacitive coupling to the adjacent sensor electrode element **805**A to compensate for the improved capacitive coupling of the sensor electrode element **801**A provided by the added sensor electrode area provided by the connection element **1608**. The area density of the sensor electrode is generally a measure of the amount of surface area of the electrode per unit area of the surface on which the sensor electrode is disposed. The area density will generally vary between a value of about one for a solid sensor electrode and some amount greater than zero (e.g., 1≈area density (AD)>0). One will note that it is assumed that the area created by the sensor electrode layer thickness times the linear length of the exposed sensor electrode layer thickness is negligible compared to the surface area of the sensor electrode that is parallel to the surface on which the sensor electrode is disposed (i.e., otherwise AD can be greater than 1). Thus, the density of the sensor electrode may be varied to provide an increased uniform response between one or more of the sensor electrodes. While sensor electrodes **802** are illustrated as having regions of differing area density, in other embodiments, one or more of the other sensor electrodes (e.g., sensor electrodes **801** and/or **805**) may have a varying area density. Further, such methods may be applied to any sensor electrode patterns described herein.

In various embodiments, the sensor electrodes **801**, **802**A-**802**D and **805**, which are illustrated in FIG. **16**A, may comprised of the same materials as the traces **1603**, **1604**A and **1604**B. In various embodiments, the sensor electrodes may be disposed in various other shapes and designs, versus a zig-zag type pattern as shown. The sensor electrode structure illustrated in the embodiment of FIG. **16**A may be combined with any other embodiment described here within.

The sensor array set **1600** may also include a shield electrode **1670** and trace routing scheme that allows the interconnection of the various traces and external components to be made outside of the sensing region **120**, such as in the external regions **1662**. The portions of the shield electrode **1670** that are disposed between the sensor electrodes and their associated traces can help reduce the cross-talk between sensor electrodes.

FIG. **17**A illustrates an alternate embodiment of a single layer sensor electrode set **1700** that includes multiple sensor electrode arrays **1710**A-**1710**D that comprise a plurality of sensor electrode groups that have an angled orientation, or herringbone orientation, relative to each other. Each group of sensor electrodes may be used to form one or more sensing elements **121** (not shown), which may be formed by sensor electrode elements **802**A and **801**A or a sensing electrode elements **802**A and **805**A. FIG. **17**B is an enlarged view of a group of sensor electrodes that may found in the sensor electrode arrays **1710**D. The angled orientation of the sensor electrode elements relative to the edges **1751** of the sensing region **120** can help maximize the sensor electrode edge length between adjacent opposing transcapacitive sensing sensor electrode types. One skilled in the art will appreciate that the capacitive coupling between adjacent sensor electrodes, such as edge **1731** (FIG. **17**B) of sensor electrode **802**A and the edge **1732** (FIG. **17**B) of sensor electrode **801**, or the edge **1731** (FIG. **17**B) of sensor electrode **802**A and the edge **1733** (FIG. **17**B) of sensor electrode **805**, is primarily created by the electric fields formed at or near these edges due to the proximity of the opposing electrodes. Typically, the surface area of a sensor electrode has a much smaller effect on the capacitive coupling between the electrodes. Therefore, by aligning the edges of the sensor electrode elements at an angle **1725** (FIG. **17**B) relative to an edge **1751** (e.g., a vertical edge **1751**) of the sensing region **120**, the lengths **1722**-**1724** of the edges **1732**-**1734** can be increased over a sensor electrode configuration that has their adjacently positioned edges aligned with an edge of the sensing region **120** (e.g., illustrated in FIGS. **10**, **12**, etc.). In some configurations, the edges **1732**, **1733** and/or **1734** formed between adjacently positioned sensor electrode elements **801**A, **802**A and/or **805**A is non-linear (not shown) to increase the adjacent or overlapping length of the sensor electrode edges. In the case the

edge(s) are non-linear, the angular alignment of the group of sensor electrodes may be found by comparing the orientation of the major axis of symmetry of the dominant sized electrode(s) found in each group of sensor electrodes or the axis of symmetry of each group of sensor electrodes

In one example, a first group of sensor electrode elements and a second group of sensor electrode elements are aligned at an angle less than or greater than 180 degrees. In one example, the first group comprises a first sensor electrode element **801**A and a second sensor electrode element **805**A that are disposed adjacent to an edge **1732** of a sensor electrode element **802**A and a second group of sensor electrode elements that comprise a first sensor electrode element **801**A and a second sensor electrode element **805**A that are disposed adjacent to an edge **1732** of a sensor electrode element **802**B, wherein the edges **1732** in the first and second groups are oriented at an angle less than or greater than 180 degrees. In this example, the angle between the edges **1732** of sensor electrode elements **802**A and **802**B may be aligned at an angle that is less than or greater than 180 degrees, wherein the angle may be defined as being equal to 180 minus twice the angle **1725** illustrated in FIG. **17**B. In one example, the angle between the edges **1732** of sensor electrode elements **802**A and **802**B is equal to about 90 degrees. In another example, the sensor electrodes (e.g., **801**, **802**, **805**) are oriented at an angle of 180 degrees such that the sensing elements **11** are distributed laterally for a single transmitter, but perpendicular to the direction of distribution of the transmitter electrodes. Furthermore, multiple sensor designs may be combined such that, for example, the substantially enclosing and alternating electrodes of FIG. **4**A are combined with the multiple receivers of FIG. **3**C and the alternating angled orientations of FIG. **17** to create an electrode element design.

While the sensor electrodes and sensor electrode elements disclosed herein may be illustrated as having specific shapes and sizes, these specific illustrations are not intended to be limiting. In various embodiments, the sensor electrodes and sensor electrode elements may have any other shape that is able to provide the necessary capacitive coupling and response. For example, some differing sensor electrode shapes that may be used singly or in pairs of opposing types of sensor electrodes are shown in FIGS. **4**A-**4**K, **5**A-**5**C, **8**, **15** and **16**A, and thus one skilled in the art will appreciate that any electrode shape illustrated herein could be used in conjunction with any other electrode shape disclosed herein without deviating from the basic scope of the invention. Further, the sensor electrodes and sensor electrode elements may have differing shapes within the same sensor electrode array. In yet other embodiments, the sensor electrodes and sensor electrodes elements may be any size, such that they provide the necessary capacitive coupling and response. Further, the size of the sensor electrodes and sensor electrode elements may be varied within a sensor electrode array. In yet other embodiments, the shape and size may be varied.

While the sensor electrode sets illustrated in FIGS. **6**B, **7**, **9**A-B, **10**, **12**A-B, **13**, **14** and **16**A all illustrate an interconnection scheme in the external region(s) **661**, **662**, **762**, **962**, **1062**, **1262**, **1362**, **1562** and **1662** that connects similarly positioned sensor electrodes together, such as the connection of the sensor electrodes positioned in the same row, this configuration is not intended to be limiting since other interconnection schemes can be used. One will note that the input device containing a sensor electrode set may be operated such that a one or more of the transmitter electrodes in the sensor electrode set may transmit at one time, while the receiver type sensor electrodes, may be operated singly or multiply to acquire resulting signals created from the transmitter signal to determine measurements of the capacitive couplings at the capacitive pixels, which are used to determine whether an input object is present and its positional information, as discussed above.

The embodiments and examples set forth herein were presented in order to best explain the present technology and its particular application and to thereby enable those skilled in the art to make and use the present technology. Those skilled in the art will recognize that the foregoing description and examples have been presented for the purposes of illustration and example only. The description as set forth is not intended to be exhaustive or to limit the present technology to the precise form disclosed. While the foregoing is directed to embodiments of the present invention, other and further embodiments of the invention may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow.

The invention claimed is:

1. A capacitive image sensor, comprising:

a first set of sensor electrodes within a first single column, the first set of sensor electrodes comprising a first sensor electrode, a second sensor electrode and a third sensor electrode, wherein the first sensor electrode is electrically coupled to the third sensor electrode via a trace, wherein the trace is disposed between two or more sensor electrodes, and wherein; and

a second set of sensor electrodes within a second single column, the second set of sensor electrodes comprising a fourth sensor electrode, a fifth sensor electrode, and a sixth sensor electrode, wherein the fourth sensor electrode is configured to capacitively couple with the first sensor electrode, and the fifth sensor electrode is configured to capacitively couple with the third sensor electrode, wherein the fourth sensor electrode, the fifth sensor electrode, and the sixth sensor electrode are independently routed.

2. The capacitive image sensor of claim **1**, wherein the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode.

3. The capacitive image sensor of claim **1**, wherein the third sensor electrode is disposed between the first sensor electrode and the second sensor electrode.

4. The capacitive image sensor of claim **1**, wherein:

the sixth sensor electrode is disposed between the fourth and fifth sensor electrodes, and

the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode, and the second sensor electrode is configured to capacitively couple with the fourth sensor electrode and the sixth sensor electrode.

5. The capacitive image sensor of claim **1**, wherein the third sixth sensor electrode has a first region and a second region, wherein the first region has an area density that is greater than the second region, and the fourth sensor electrode is disposed adjacent to the first region and the fifth sensor electrode is disposed adjacent to the second region.

6. The capacitive image sensor of claim **1**, wherein the first sensor electrode and the second sensor electrode are disposed adjacent to an edge of the fourth sensor electrode and the third sensor electrode is disposed adjacent to an edge of the fifth sensor electrode, and

wherein the edge of the fourth sensor electrode and the edge of the fifth sensor electrode are aligned at an angle less than or greater than 180 degrees.

7. The capacitive image sensor of claim **1**, wherein the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode, and the second sen-

sor electrode has a first protrusion that is disposed between the first sensor electrodes and the trace that electrically couples the first sensor electrode to the third sensor electrode.

8. A capacitive image sensor comprising:

a substrate;

a plurality of traces disposed on a first surface of the substrate,

a plurality of sensor electrodes disposed on a first surface of the substrate, the plurality of sensor electrodes comprises:

a first set of sensor electrodes within a first single column, the first set of sensor electrodes comprising a first sensor electrode, a second sensor electrode and a third sensor electrode, wherein the first sensor electrode is electrically coupled to the third sensor electrode via a first trace of the plurality of traces; and

a second set of sensor electrodes within a second single column, the second set of sensor electrodes comprising a fourth sensor electrode, a fifth sensor electrode, and a sixth sensor electrode, wherein the fourth sensor electrode is configured to capacitively couple with the first sensor electrode and the fifth sensor electrode is configure to capacitively couple with the third sensor electrode, wherein the first trace is disposed between the fourth sensor electrode and the sixth sensor electrode, wherein the second sensor electrode is configured to capacitively couple with the fourth sensor electrode and the sixth sensor electrode, and wherein the fourth sensor electrode, the fifth sensor electrode, and the sixth sensor electrode are independently routed; and

a processing system communicatively coupled to the plurality of sensor electrodes and configured to:

transmit transmitter signals with one of the first sensor electrode and the fourth sensor electrode;

receive resulting signals with the other of the first sensor electrode and the fourth sensor electrode, the resulting signals comprising effects corresponding to the transmitter signal; and

determine positional information for an input object based on measurement of a change in the capacitive coupling between the first sensor electrode and the fourth sensor electrode, the measurement based on the resulting signals.

9. The capacitive image sensor of claim **8**, wherein the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode.

10. The capacitive image sensor of claim **8**, wherein the third sensor electrode is disposed between the first sensor electrode and the second sensor electrode.

11. The capacitive image sensor of claim **8**, wherein:

the sixth sensor electrode is disposed between the fourth and fifth sensor electrodes, and

the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode.

12. The capacitive image sensor of claim **8**, wherein the sixth sensor electrode has a first region and a second region, wherein the first region has an area density that is greater than the second region, and the fourth sensor electrode is disposed adjacent to the first region and the fifth sensor electrode is disposed adjacent to the second region.

13. A capacitive image sensor, comprising:

a first set of sensor electrodes comprising a first sensor electrode, a second sensor electrode, and a third sensor electrode disposed within a first single column; and

a second set of sensor electrodes comprising a fourth independently routed sensor electrode, a fifth independently routed sensor electrode, and a sixth independently routed sensor electrode disposed within a second single column,

wherein the first sensor electrode is electrically coupled to the third sensor electrode via a trace disposed between two or more sensor electrodes, and

wherein the fifth sensor electrode is configured to capacitively couple with the third sensor electrode and the second sensor electrode is configured to capacitively couple with the fourth sensor electrode and the sixth sensor electrode.

14. The capacitive image sensor of claim **13**, wherein the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode.

15. The capacitive image sensor of claim **13**, wherein the third sensor electrode is disposed between the first sensor electrode and the second sensor electrode.

16. The capacitive image sensor of claim **13**, wherein:

the sixth sensor electrode is disposed between the fourth and fifth sensor electrodes, and

the second sensor electrode is disposed between the first sensor electrode and the third sensor electrode.

17. The capacitive image sensor of claim **13**, wherein the sixth sensor electrode has a first region and a second region, wherein the first region has an area density that is greater than the second region, and the fourth sensor electrode is disposed adjacent to the first region and the fifth sensor electrode is disposed adjacent to the second region.

* * * * *